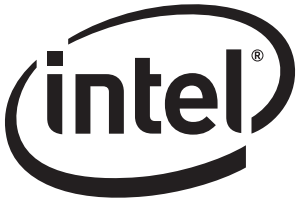

Intel® Desktop Board DP43BF

Technical Product Specification

March 2010
Order Number: E89938-001US

The Intel® Desktop Board DP43BF may contain design defects or errors known as errata that may cause the product to deviate from published specifications. Current characterized errata are documented in the Intel Desktop Board DP43BF Specification Update.

Revision History

Revision	Revision History	Date
-001	First release of the Intel® Desktop Board DP43BF Technical Product Specification.	March 2010

This product specification applies to only the standard Intel® Desktop Board DP43BF with BIOS identifier RKG4310H.86A

Changes to this specification will be published in the Intel Desktop Board DP43BF Specification Update before being incorporated into a revision of this document.

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Preface

This Technical Product Specification (TPS) specifies the board layout, components, connectors, power and environmental requirements, and the BIOS for the Intel® Desktop Board DP43BF. It describes the standard product and available manufacturing options.

Intended Audience

The TPS is intended to provide detailed, technical information about the Intel Desktop Board DP43BF and its components to the vendors, system integrators, and other engineers and technicians who need this level of information. It is specifically *not* intended for general audiences.

What This Document Contains

Chapter	Description
1	A description of the hardware used on the board
2	A map of the resources of the board
3	The features supported by the BIOS Setup program
4	A description of the BIOS error messages, beep codes, and POST codes
5	Regulatory compliance and battery disposal information

Typographical Conventions

This section contains information about the conventions used in this specification. Not all of these symbols and abbreviations appear in all specifications of this type.

Notes, Cautions, and Warnings

NOTE

Notes call attention to important information.

CAUTION

Cautions are included to help you avoid damaging hardware or losing data.

Other Common Notation

#	Used after a signal name to identify an active-low signal (such as USBP0#)
GB	Gigabyte (1,073,741,824 bytes)
GB/s	Gigabytes per second
Gb	Gigabit (1,073,741,824 bits)
Gb/s	Gigabits per second
KB	Kilobyte (1024 bytes)
Kb	Kilobit (1024 bits)
kb/s	1000 bits per second
MB	Megabyte (1,048,576 bytes)
MB/s	Megabytes per second
Mb	Megabit (1,048,576 bits)
Mb/s	Megabits per second
xxh	An address or data value ending with a lowercase h indicates a hexadecimal value.
x.x V	Volts. Voltages are DC unless otherwise specified.
*	This symbol is used to indicate third-party brands and names that are the property of their respective owners.

Contents

1 Product Description

1.1 Overview 9
1.1.1 Feature Summary 9
1.1.2 Board Layout 11
1.1.3 Block Diagram 13
1.2 Legacy Considerations 14
1.3 Online Support 14
1.4 Processor 15
1.5 System Memory 16
1.5.1 Memory Configurations 17
1.6 Intel® P43 Express Chipset 19
1.6.2 USB 19
1.6.3 ATA Support 20
1.7 Real-Time Clock Subsystem 22
1.8 Legacy I/O Controller 22
1.8.1 Serial Port 22
1.9 Audio Subsystem 23
1.9.1 Audio Subsystem Software 24
1.9.2 Audio Connectors and Headers 24
1.10 LAN Subsystem 25
1.10.1 Broadcom BCM57788 Gigabit Ethernet Controller 25
1.10.2 LAN Subsystem Software 25
1.10.3 RJ-45 LAN Connector with Integrated LEDs 26
1.11 Hardware Management Subsystem 27
1.11.1 Hardware Monitoring and Fan Control 27
1.11.2 Fan Monitoring 27
1.11.3 Chassis Intrusion Detection 27
1.11.4 Thermal Monitoring 28
1.12 Power Management 29
1.12.1 ACPI 29
1.12.2 Hardware Support 32
1.12.3 ENERGY STAR* 5.0, e-Standby, and ErP Compliance 36

2 Technical Reference

2.1 Memory Map 37
2.1.1 Addressable Memory 37
2.2 Connectors and Headers 40
2.2.1 Back Panel Connectors 41
2.2.2 Component-side Connectors and Headers 42
2.3 BIOS Configuration Jumper Block 52
2.4 Mechanical Considerations 53
2.4.1 Form Factor 53
2.5 Electrical Considerations 54

2.5.1 Power Supply Considerations 54
2.5.2 Fan Header Current Capability 54
2.5.3 Add-in Board Considerations 55
2.6 Thermal Considerations 55
2.7 Reliability 57
2.8 Environmental 57

3 Overview of BIOS Features

3.1 Introduction 59
3.2 BIOS Flash Memory Organization 60
3.3 Resource Configuration 60
3.3.1 PCI* Autoconfiguration 60
3.4 System Management BIOS (SMBIOS) 61
3.5 Legacy USB Support 62
3.6 BIOS Updates 63
3.6.1 Language Support 63
3.6.2 Custom Splash Screen 63
3.7 BIOS Recovery 64
3.8 Boot Options 64
3.8.1 Optical Drive Boot 64
3.8.2 Network Boot 64
3.8.3 Booting Without Attached Devices 65
3.8.4 Changing the Default Boot Device During POST 65
3.9 Adjusting Boot Speed 65
3.9.1 Peripheral Selection and Configuration 65
3.9.2 BIOS Boot Optimizations 66
3.10 BIOS Security Features 67

4 Error Messages and Beep Codes

4.1 Speaker 69
4.2 BIOS Beep Codes 69
4.3 Front-panel Power LED Blink Codes 70
4.4 BIOS Error Messages 70
4.5 Port 80h POST Codes 71

5 Regulatory Compliance and Battery Disposal Information

5.1 Regulatory Compliance 77
5.1.1 Safety Standards 77
5.1.2 European Union Declaration of Conformity Statement 78
5.1.3 Product Ecology Statements 79
5.1.4 EMC Regulations 83
5.1.5 Product Certification Markings (Board Level) 84
5.2 Battery Disposal Information 85

Figures

1. Major Board Components 11
2. Block Diagram 13
3. Memory Channel and DIMM Configuration 18
4. Back Panel Audio Connectors 24
5. LAN Connector LED Locations 26
6. Thermal Sensors and Fan Headers 28
7. Location of the Standby Power Indicator LED 35
8. Detailed System Memory Address Map 38
9. Back Panel Connectors 41
10. Component-side Connectors and Headers 42
11. Connection Diagram for Front Panel Header 48
12. Connection Diagram for Front Panel USB Headers 50
13. Connection Diagram for IEEE 1394a Header 51
14. Location of the BIOS Configuration Jumper Block 52
15. Board Dimensions 53
16. Localized High Temperature Zones 56

Tables

1. Feature Summary 9
2. Board Components Shown in Figure 1 12
3. Supported Memory Configurations 16
4. Audio Jack Retasking Support 23
5. LAN Connector LED States 26
6. Effects of Pressing the Power Switch 29
7. Power States and Targeted System Power 30
8. Wake-up Devices and Events 31
9. System Memory Map 39
10. Component-side Connectors and Headers Shown in Figure 10 43
11. Front Panel Audio Header for HD Audio 44
12. Front Panel Audio Header for AC ’97 Audio 44
13. Serial ATA Connectors 44
14. Serial Port Header 44
15. PATA Connector (44-Pin) 45
16. S/PDIF Header 45
17. Chassis Intrusion Header 46
18. Processor (4-Pin) Fan Header 46
19. Front, Rear, and Auxiliary Chassis Fan Headers 46
20. Processor Core Power Connector 47
21. Main Power Connector 47
22. Front Panel Header 48
23. States for a One-Color Power LED 49
24. States for a Two-Color Power LED 49
25. Alternate Front Panel Power LED Header 50
26. BIOS Setup Configuration Jumper Settings 52
27. Recommended Power Supply Current Values 54

28. Fan Header Current Capability 54
29. Thermal Considerations for Components 56
30. Intel Desktop Board DP43BF Environmental Specifications 57
31. BIOS Setup Program Menu Bar 60
32. BIOS Setup Program Function Keys 60
33. Acceptable Drives/Media Types for BIOS Recovery 64
34. Boot Device Menu Options 65
35. Supervisor and User Password Functions 67
36. BIOS Beep Codes 69
37. Front-panel Power LED Blink Codes 70
38. BIOS Error Messages 70
39. Port 80h POST Code Ranges 71
40. Port 80h POST Codes 72
41. Typical Port 80h POST Sequence 75
42. Safety Standards 77
43. Lead-Free Board Markings 82
44. EMC Regulations 83
45. Product Certification Markings 84

1 Product Description

1.1 Overview

1.1.1 Feature Summary

Table 1 summarizes the major features of Intel Desktop Board DP43BF.

Table 1. Feature Summary

Form Factor	ATX (9.60 inches by 11.60 inches [243.84 millimeters by 294.64 millimeters])
Processor	Support for the following: • Intel® Core™2 Quad processor Q6000/Q8000/Q9000 Series in an LGA775 socket • Intel® Core™2 Duo processor E4000/E6000/E7000/E8000 Series in an LGA775 socket • Intel® Pentium® Dual-Core processor E2000/E5000 Series in an LGA775 socket • Intel® Celeron® Dual-Core processor 400/1000 Series in an LGA775 socket • Intel® Xeon® processor 3000/X3000 Series in an LGA775 socket
Memory	• Four 240-pin DDR3 SDRAM Dual Inline Memory Module (DIMM) sockets • Support for up to 8 GB of system memory using non-ECC DDR3 800, 1066, or 1333 (OC) MHz DIMMs
Chipset	Intel® P43 Express Chipset, consisting of: • Intel® 82P43 Graphics and Memory Controller Hub (MCH) • Intel® 82801JIR I/O Controller Hub (Intel ICH10R)
Audio	10-channel (7.1 + 2) audio subsystem using Realtek ALC888S-VC high definition audio codec
Legacy I/O Control	ITE IT8721F based legacy I/O controller for hardware management and serial and PS/2* ports
Peripheral Interfaces	• Twelve USB 2.0 ports: — Six ports are implemented with stacked back panel connectors — Six ports are routed to three separate front panel headers • Two IEEE 1394a ports: — One back panel port — One front panel header • Five internal Serial ATA (SATA) interfaces • One external Serial ATA (eSATA) interface • One Parallel ATA (PATA) connector • One serial port header • PS/2 keyboard/mouse ports on the back panel

continued

Table 1. Feature Summary

LAN Support	Gigabit (10/100/1000 Mb/s) LAN subsystem using the Broadcom* BCM57788 Gigabit Ethernet Controller
BIOS	• Intel® BIOS (resident in the SPI Flash device) • Support for Advanced Configuration and Power Interface (ACPI), Plug and Play, and SMBIOS
Instantly Available PC Technology	• Support for PCI* Local Bus Specification Revision 2.3 • Support for PCI Express* Revision 1.1 • Suspend to RAM support • Wake on PCI, PCI Express, PS/2 devices, serial port, front panel, USB ports, and LAN
Expansion Capabilities	• One PCI Express 2.0 x16 bus add-in card connector • Two PCI Express 1.0 x1 bus add-in card connectors • Four Conventional PCI bus add-in card connectors
Hardware Monitor Subsystem	• Voltage sense to detect out of range power supply voltages • Thermal sense to detect out of range thermal values • Three fan headers • Three fan sense inputs used to monitor fan activity

1.1.2 Board Layout

Figure 1 shows the location of the board's major components.

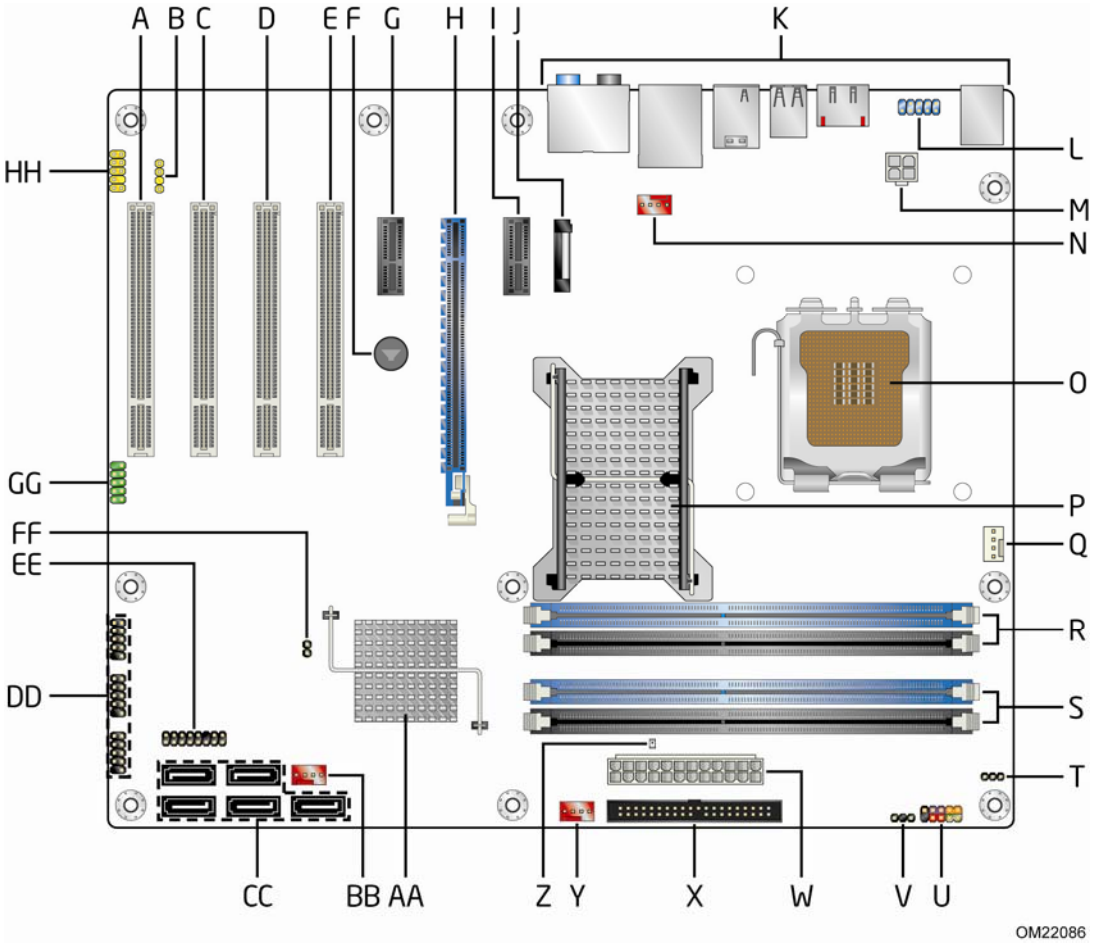


Figure 1. Major Board Components

Table 2 lists the components identified in Figure 1.

Table 2. Board Components Shown in Figure 1

Item/callout from Figure 1	Description
A	Conventional PCI bus add-in card connector
B	S/PDIF audio header
C	Conventional PCI bus add-in card connector
D	Conventional PCI bus add-in card connector
E	Conventional PCI bus add-in card connector
F	Speaker
G	PCI Express x1 connector
H	PCI Express x16 connector
I	Conventional PCI bus add-in card connector
J	Battery
K	Back panel connectors
L	Front panel IEEE 1394a header
M	Processor core power connector (2 x 2)
N	Rear chassis fan header
O	LGA775 processor socket
P	Intel 82P43 MCH
Q	Processor fan header
R	DIMM Channel A sockets
S	DIMM Channel B sockets
T	BIOS setup configuration jumper block
U	Front panel header
V	Alternate front panel Power LED header
W	Main power connector (2 x 12)
X	Parallel ATA connector
Y	Front chassis fan header
Z	Standby power LED
AA	Intel 82801JIR I/O Controller Hub (Intel ICH10R)
BB	Auxiliary chassis fan header
CC	Serial ATA connectors (5)
DD	Front panel USB headers
EE	Intel® High Definition Audio Link header
FF	Chassis intrusion header
GG	Serial port header
HH	Front panel audio header

1.1.3 Block Diagram

Figure 2 is a block diagram of the board's major functional areas.

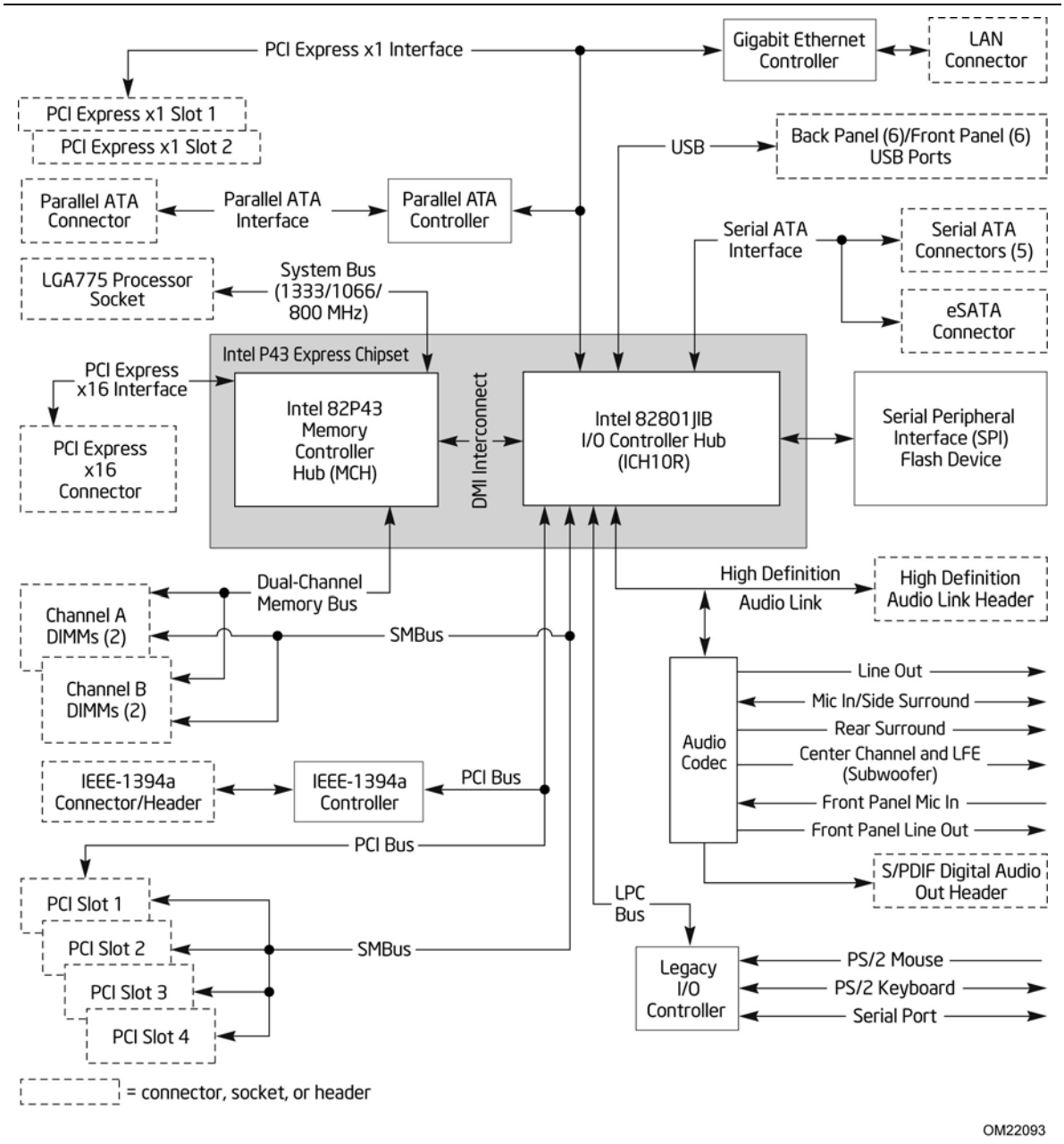


Figure 2. Block Diagram

1.2 Legacy Considerations

This board differs from other Intel® Desktop Board products, with specific changes including (but not limited to) the following:

- No floppy drive connector
- No parallel port connector on the back panel
- No serial port connector on the back panel

1.3 Online Support

To find information about…	Visit this World Wide Web site:
Intel Desktop Board DP43BF	http://www.intel.com/products/motherboard/DP43BF/index.htm
Desktop Board Support	http://www.intel.com/support/motherboards/desktop
Available configurations for the Intel Desktop Board DP43BF	http://www.intel.com/products/motherboard/DP43BF/index.htm
Supported processors	http://processormatch.intel.com
Chipset information	http://www.intel.com/products/desktop/chipsets/index.htm
BIOS and driver updates	http://downloadcenter.intel.com
Tested memory	http://www.intel.com/support/motherboards/desktop/sb/CS-025414.htm
Integration information	http://www.intel.com/support/go/buildit

1.4 Processor

The board is designed to support the following processors:

- Intel® Core™2 Quad processor Q6000/Q8000/Q9000 Series in an LGA775 socket
- Intel® Core™2 Duo processor E4000/E6000/E7000/E8000 Series in an LGA775 socket
- Intel® Pentium® Dual-Core processor E2000/E5000 Series in an LGA775 socket
- Intel® Celeron® Dual-Core processor 400/1000 Series in an LGA775 socket
- Intel® Xeon® processor 3000/X3000 Series in an LGA775 socket

Other processors may be supported in the future. This board is designed to support processors with a maximum wattage of 95 W. The processors listed above are only supported when falling within the wattage requirements of the board. See the Intel web site listed below for the most up-to-date list of supported processors.

For information about…	Refer to:
Supported processors	http://processormatch.intel.com

CAUTION

Use only the processors listed on the web site above. Use of unsupported processors can damage the board, the processor, and the power supply.

NOTE

Use only ATX12V-compliant power supplies.

For information about	Refer to
Power supply connectors	Section 2.2.2.3, page 47

1.5 System Memory

The board has four DIMM sockets and supports the following memory features:

- 1.8 V DDR3 800 MHz, DDR3 1066 MHz, and DDR3 1333 (OC) MHz SDRAM DIMMs
- Two independent memory channels with interleaved mode support
- Unbuffered, single-sided or double-sided DIMMs with the following restriction:
  Double-sided DIMMs with x16 organization are not supported.
- 8 GB maximum total system memory (with 2 Gb memory technology). Refer to Section 2.1.1 on page 37 for information on the total amount of addressable memory.
- Minimum total system memory: 512 MB
- Non-ECC DIMMs
- Serial Presence Detect

NOTE

To be fully compliant with all applicable DDR SDRAM memory specifications, the board should be populated with DIMMs that support the Serial Presence Detect (SPD) data structure. This allows the BIOS to read the SPD data and program the chipset to accurately configure memory settings for optimum performance. If non-SPD memory is installed, the BIOS will attempt to correctly configure the memory settings, but performance and reliability may be impacted or the DIMMs may not function under the determined frequency.

Table 3 lists the supported DIMM configurations.

Table 3. Supported Memory Configurations

DIMM Capacity	Configuration (Note)	SDRAM Density	SDRAM Organization Front-side/Back-side	Number of SDRAM Devices
1024 MB	SS	1 Gbit	1 Gb x8/empty	8
2048 MB	DS	1 Gbit	1 Gb x8/1 Gb x8	16
2048 MB	SS	2 Gbit	2 Gb x8/empty	8
4096 MB	DS	2 Gbit	2 Gb x8/2 Gb x8	16

Note: "DS" refers to double-sided memory modules (containing two rows of SDRAM) and "SS" refers to single-sided memory modules (containing one row of SDRAM).

1.5.1 Memory Configurations

The Intel 82P43 MCH supports the following types of memory organization:

- **Dual channel (Interleaved) mode**. This mode offers the highest throughput for real world applications. Dual channel mode is enabled when the installed memory capacities of both DIMM channels are equal. Technology and device width can vary from one channel to the other but the installed memory capacity for each channel must be equal. If different speed DIMMs are used between channels, the slowest memory timing will be used.
- **Single channel (Asymmetric) mode**. This mode is equivalent to single channel bandwidth operation for real world applications. This mode is used when only a single DIMM is installed or the memory capacities are unequal. Technology and device width can vary from one channel to the other. If different speed DIMMs are used between channels, the slowest memory timing will be used.
- **Flex mode**. This mode provides the most flexible performance characteristics. The bottommost DRAM memory (the memory that is lowest within the system memory map) is mapped to dual channel operation; the topmost DRAM memory (the memory that is nearest to the 8 GB address space limit), if any, is mapped to single channel operation. Flex mode results in multiple zones of dual and single channel operation across the whole of DRAM memory. To use flex mode, it is necessary to populate both channels.

For information about…	Refer to:
Memory Configuration Examples	http://www.intel.com/support/motherboards/desktop/sb/cs-011965.htm

Figure 3 illustrates the memory channel and DIMM configuration.

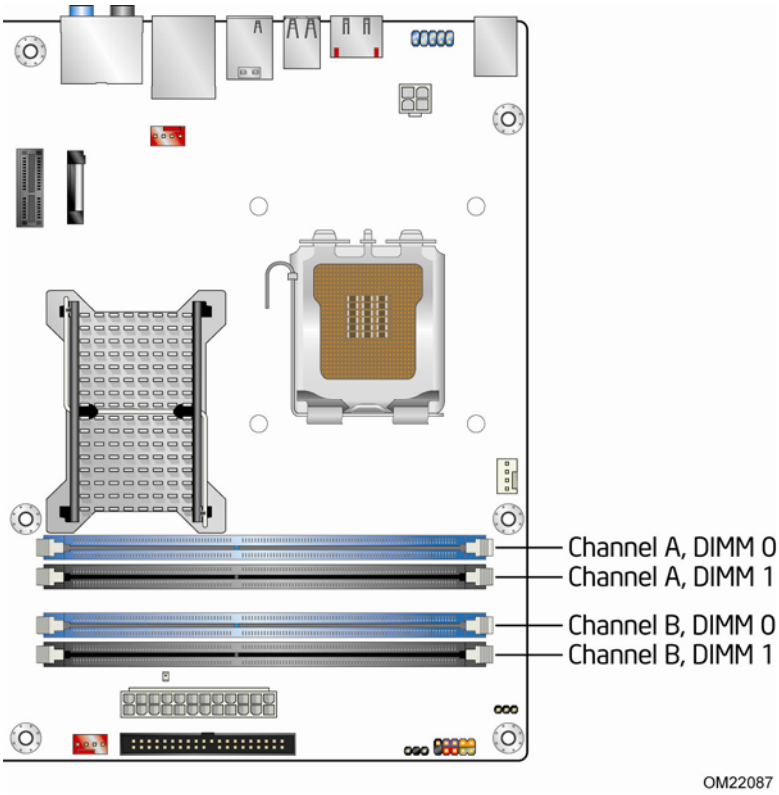


Figure 3. Memory Channel and DIMM Configuration

1.6 Intel® P43 Express Chipset

The Intel P43 Express chipset consists of the following devices:

- Intel 82P43 Memory Controller Hub (MCH) with Direct Media Interface (DMI) interconnect
- Intel 82801JIR I/O Controller Hub (ICH10R)

The MCH component provides interfaces to the CPU, memory, PCI Express, and the DMI interconnect. The ICH10R is a centralized controller for the board's I/O paths.

The chipset supports the following features:

- USB
- Serial ATA
- Parallel ATA

For information about	Refer to
The Intel P43 Express chipset	http://www.intel.com/products/desktop/chipsets/index.htm
Resources used by the chipset	Chapter 2

1.6.1.1 PCI Express x16 Graphics

The MCH also supports an add-in discrete graphics card through the PCI Express 2.0 graphics connector.

- PCI Express 2.0 x16:
  - Supports PCI Express GEN1 frequency of 1.25 GHz resulting in 2.5 Gb/s each direction (500 MB/s total). Maximum theoretical bandwidth on interface of 4 GB/s in each direction simultaneously, for an aggregate of 8 GB/s when operating in x16 mode.
  - Supports PCI Express GEN2 frequency of 2.5 GHz resulting in 5.0 Gb/s each direction (1000 MB/s total). Maximum theoretical bandwidth on interface of 8 GB/s in each direction simultaneously, for an aggregate of 16 GB/s when operating in x16 mode.

For information about	Refer to
PCI Express technology	http://www.pcisig.com

1.6.2 USB

The board supports up to twelve USB 2.0 ports, supports UHCI and EHCI, and uses UHCI- and EHCI-compatible drivers.

The Intel ICH10R provides the USB controller for all ports. The port arrangement is as follows:

- Six ports are implemented with stacked back panel connectors
- Six ports are routed to three separate front panel USB headers

For information about	Refer to
The location of the USB connectors on the back panel	Figure 9, page 41
The location of the front panel USB headers	Figure 10, page 42

1.6.3 ATA Support

The board provides seven ATA interface connectors:

- One PATA connector that supports two devices
- Five SATA connectors that support one device per connector
- One eSATA connector

1.6.3.1 PATA Interface

The discrete PATA controller has one bus-mastering PATA interface that is accessible through a 44-pin connector. The PATA interface supports the following modes:

- Programmed I/O (PIO): processor controls data transfer.
- 8237-style DMA: DMA offloads the processor, supporting transfer rates of up to 16 MB/s.
- Ultra DMA: DMA protocol on ATA bus supporting host and target throttling and transfer rates of up to 33 MB/s.
- ATA-66: DMA protocol on ATA bus supporting host and target throttling and transfer rates of up to 66 MB/s. ATA-66 protocol is similar to Ultra DMA and is device driver compatible.
- ATA-100: DMA protocol on ATA bus allows host and target throttling. The controller's ATA-100 logic can achieve read transfer rates up to 100 MB/s and write transfer rates up to 88 MB/s.

NOTE

ATA-66 and ATA-100 are faster timings and require a specialized cable to reduce reflections, noise, and inductive coupling.

The PATA interface also supports ATAPI devices (such as optical drives) and ATA devices using the transfer modes.

The BIOS supports Logical Block Addressing (LBA) and Extended Cylinder Head Sector (ECHS) translation modes. The drive reports the transfer rate and translation mode to the BIOS.

For information about	Refer to
The location of the PATA connector	Figure 10, page 42

1.6.3.2 SATA Interfaces

The board provides six SATA connectors through the PCH, which support one device per connector:

- Five internal SATA connectors (black)
- One eSATA connector (red) on the back panel for external connectivity

The Intel ICH10R SATA controller provides independent SATA ports with a theoretical maximum transfer rate of 3 Gb/s per port. A point-to-point interface is used for host to device connections.

For compatibility, the underlying SATA functionality is transparent to the operating system. The SATA controller supports IDE and AHCI (Microsoft Windows Vista* only) configuration and can operate in both legacy and native modes. In legacy mode, standard ATA I/O and IRQ resources are assigned (IRQ 14 and 15). In Native mode, standard Conventional PCI bus resource steering is used. Native mode is the preferred mode for configurations using the Windows* XP and Windows Vista operating systems.

For information about	Refer to
Obtaining AHCI driver	Section 1.3, page 14
The location of the SATA connectors	Figure 10, page 42

1.6.3.2.1 Serial ATA RAID

The board supports the Intel® Matrix Storage Technology which provides the following RAID (Redundant Array of Independent Drives) levels:

- **RAID 0** - data striping
- **RAID 1** - data mirroring
- **RAID 0+1 (or RAID 10)** - data striping and mirroring
- **RAID 5** - distributed parity

1.6.3.2.2 Intel® Rapid Recover Technology

The board incorporates the Intel® Rapid Recover Technology (Intel® RRT). Intel® Rapid Recover Technology is a feature of Intel® Matrix Storage Manager. It uses RAID 1 (mirroring) functionality to copy data from a designated master drive to a designated recovery drive. The master drive data can be copied to the recovery drive either continuously or on request.

When using the continuous update policy, changes made to the data on the master drive while the recovery drive is disconnected or offline are automatically copied to the recovery drive when it is reconnected. When using the on request update policy, the master drive data can be restored to a previous state by copying the data on the recovery drive back to the master drive.

For information about	Refer to
Intel® Matrix Storage and Intel® Rapid Recovery Technology	http://www.intel.com/design/chipsets/matrixstorage_sb.htm

1.7 Real-Time Clock Subsystem

A coin-cell battery (CR2032) powers the real-time clock and CMOS memory. When the computer is not plugged into a wall socket, the battery has an estimated life of three years. When the computer is plugged in, the standby current from the power supply extends the life of the battery. The clock is accurate to ± 13 minutes/year at 25 ºC with 3.3 VSB applied.

NOTE

If the battery and AC power fail, custom defaults, if previously saved, will be loaded into CMOS RAM at power-on.

When the voltage drops below a certain level, the BIOS Setup program settings stored in CMOS RAM (for example, the date and time) might not be accurate. Replace the battery with an equivalent one. Figure 1 on page 11 shows the location of the battery.

1.8 Legacy I/O Controller

The Legacy I/O controller provides the following features:

- One serial port header
- PS/2-style keyboard/mouse interfaces
- Serial IRQ interface compatible with serialized IRQ support for PCI systems
- Intelligent power management, including a programmable wake-up event interface
- Conventional PCI bus power management support

The BIOS Setup program provides configuration options for the I/O controller.

1.8.1 Serial Port

The board has one serial port header located on the component side of the board. The serial port supports data transfers at speeds up to 115.2 kb/s with BIOS support.

For information about	Refer to
The location of the serial port header	Figure 10, page 42
The signal names of the serial port header	Table 14, page 44

1.9 Audio Subsystem

The audio subsystem consists of the following:

- Intel 82801JIR (Intel ICH10R)
- Realtek ALC888S-VC audio codec

The audio subsystem supports the following audio connectors and headers:

- S/PDIF header
- Front panel audio header with support for Intel® High Definition Audio (Intel® HD Audio) and AC '97 audio
- Back panel audio connectors

NOTE

Systems built with an AC '97 audio front panel will not be able to obtain the Microsoft Windows Vista logo.

Table 4 lists the supported functions of the front panel and back panel audio jacks.

Table 4. Audio Jack Retasking Support

Audio Jack	Micro-phone	Head-phones	Front Speaker	Line In	Side Surround	Rear Surround	Center/ Sub
FP Green		Default	Ctrl panel				
FP Pink	Default						
Rear Blue		Ctrl panel		Default	Ctrl panel		
Rear Green		Ctrl panel	Default				
Rear Pink	Default						
Rear Black						Default	
Rear Orange							Default

1.9.1 Audio Subsystem Software

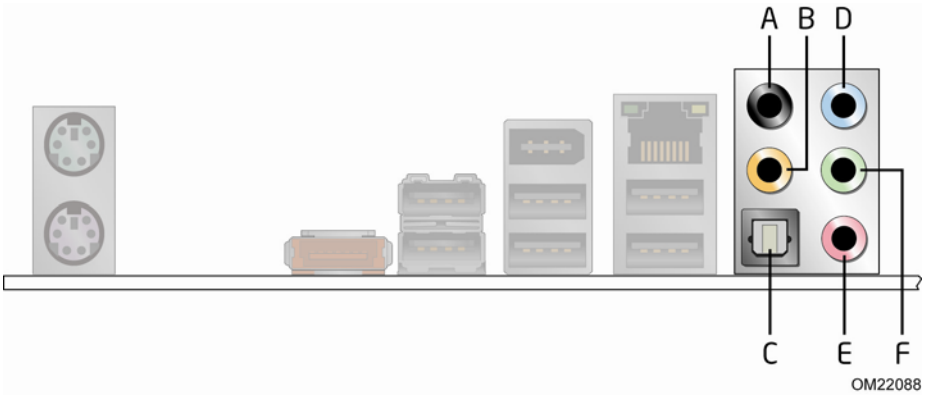
Audio software and drivers are available from Intel's World Wide Web site.

For information about	Refer to
Obtaining audio software and drivers	Section 1.2, page 14

1.9.2 Audio Connectors and Headers

The board contains audio connectors on the back panel and audio headers on the component side of the board. The front panel audio header provides mic in and line out signals for the front panel. Microphone bias is supported for both the front and back panel microphone connectors.

The front/back panel audio connectors and headers are configurable through the audio device drivers. The available configurable back panel audio connectors are shown in Figure 4.



Item	Description
A	Rear surround
B	Center channel and LFE (subwoofer) audio out
C	S/PDIF digital audio out (optical)
D	Headphones/line in/side surround
E	Mic in
F	Headphones/front speaker

Figure 4. Back Panel Audio Connectors

For information about	Refer to
The location of the front panel audio header	Figure 10, page 42
The signal names of the front panel audio header	Table 11, page 44

1.10 LAN Subsystem

The LAN subsystem consists of the following:

- Broadcom BCM57788 Gigabit Ethernet Controller (10/100/1000 Mb/s)
- Intel 82801JIR (Intel ICH10R)
- RJ-45 LAN connector with integrated status LEDs

Additional features of the LAN subsystem include:

- CSMA/CD protocol engine
- LAN connect interface between Intel ICH10R and the LAN controller
- Conventional PCI bus power management
  - ACPI technology support
  - LAN wake capabilities
- LAN subsystem software

For information about	Refer to
LAN software and drivers	http://downloadcenter.intel.com

1.10.1 Broadcom BCM57788 Gigabit Ethernet Controller

The Broadcom BCM57788 Gigabit Ethernet Controller supports the following features:

- PCI Express link
- 10/100/1000 IEEE 802.3 compliant
- Compliant to IEEE 802.3x flow control support
- 802.1p
- TCP, IP, and UDP checksum offload (for IPv4 and IPv6)
- Wake-on-LAN (WOL) support meeting ACPI requirements
- Full device driver compatibility
- PCI Express power management support

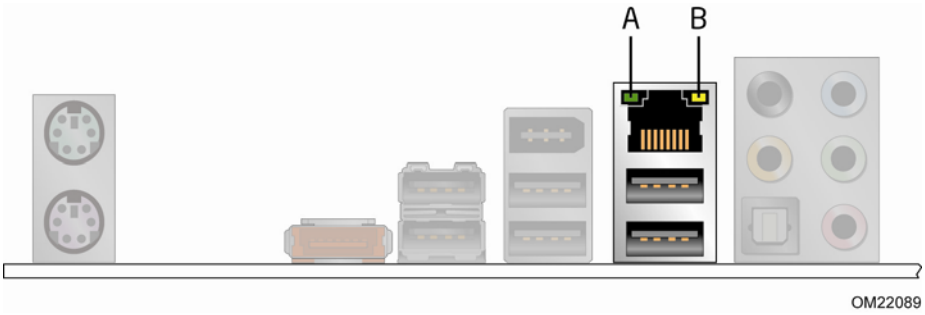
1.10.2 LAN Subsystem Software

LAN software and drivers are available from Intel's World Wide Web site.

For information about	Refer to
Obtaining LAN software and drivers	Section 1.2, page 14

1.10.3 RJ-45 LAN Connector with Integrated LEDs

Two LEDs are built into the RJ-45 LAN connector (shown in Figure 5).



Item	Description
A	Link LED (Green)
B	Data Rate LED (Green/Yellow)

Figure 5. LAN Connector LED Locations

Table 5 describes the LED states when the board is powered up and the LAN subsystem is operating.

Table 5. LAN Connector LED States

LED	Color	State	Condition
Link (A)	N/A	Off	LAN link is not established
	Green	On	LAN link is established
		Blinking	LAN activity occurring
Speed (B)	N/A	Off	10 Mb/s data rate
	Green	On	100 Mb/s data rate
	Yellow	On	1000 Mb/s data rate

1.11 Hardware Management Subsystem

The hardware management features enable the board to be compatible with the Wired for Management (WfM) specification. The board has several hardware management features, including the following:

- Fan monitoring and control
- Thermal and voltage monitoring
- Chassis intrusion detection

1.11.1 Hardware Monitoring and Fan Control

The features of the hardware monitoring and fan control include:

- Fan speed control controllers and sensors integrated into the Intel ICH10R
- Remote thermal diode sensor for ambient temperature sensing
- Thermal sensors in the processor, Intel 82P43 MCH, and Intel 82801JIR (Intel ICH10R)
- Power supply monitoring of five voltages (+5 V, +12 V, +3.3 V, +1.125 V, and +VCCP) to detect levels above or below acceptable values
- Thermally monitored closed-loop fan control, for all three fans, that can adjust the fan speed according to thermal conditions

1.11.2 Fan Monitoring

Fan monitoring can be implemented using Intel® Desktop Utilities or third-party software.

For information about	Refer to
The functions of the fan headers	Section 1.12.2.2, page 33

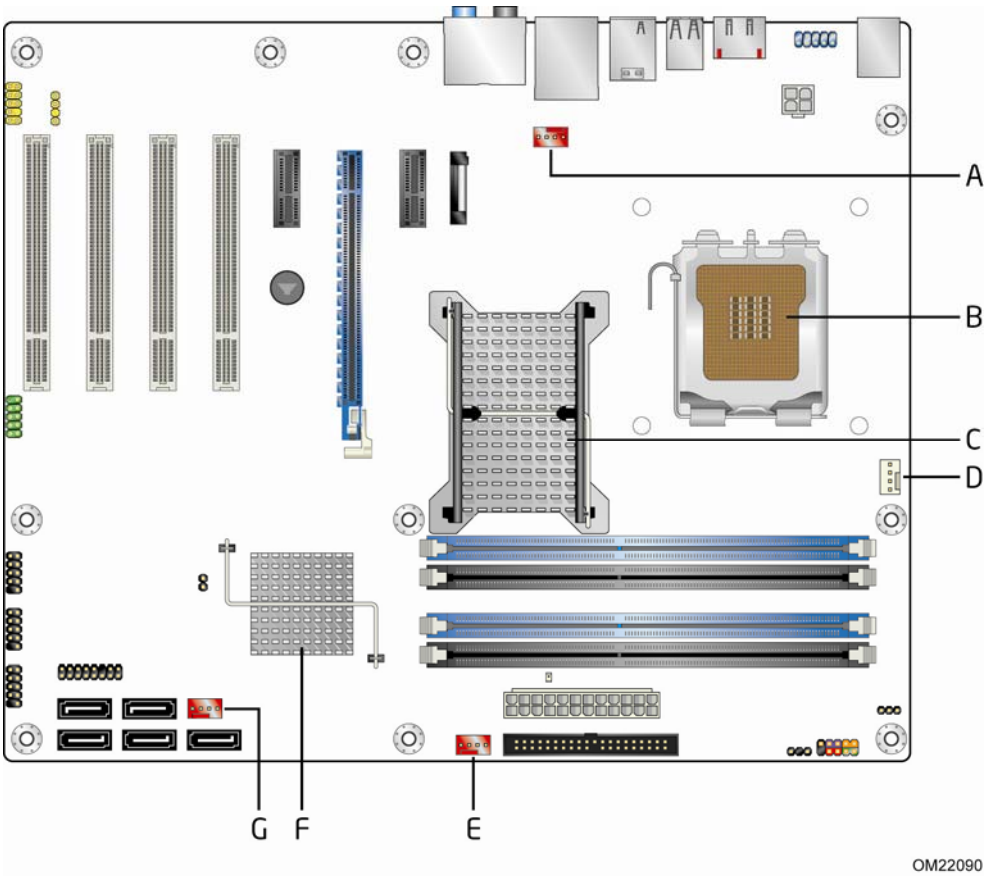
1.11.3 Chassis Intrusion Detection

The board supports a chassis security feature that detects if the chassis cover is removed. The security feature uses a mechanical switch on the chassis that attaches to the chassis intrusion header. When the chassis cover is removed, the mechanical switch is in the closed position.

For information about	Refer to
The location of the chassis intrusion header	Figure 10, page 42

1.11.4 Thermal Monitoring

Figure 6 shows the locations of the thermal sensors and fan headers.



Item	Description
A	Rear chassis fan header
B	Thermal diode, located on the processor die
C	Thermal diode, located on the MCH die
D	Processor fan header
E	Front chassis fan header
F	Thermal diode, located on the Intel ICH10R die
G	Auxiliary chassis fan header

Figure 6. Thermal Sensors and Fan Headers

NOTE

The minimum thermal reporting threshold for the MCH is 66 °C. The MCH thermal sensor will display 66 °C until the temperature rises above this point.

1.12 Power Management

Power management is implemented at several levels, including:

- Software support through Advanced Configuration and Power Interface (ACPI)
- Hardware support:
  - Power connector
  - Fan headers
  - LAN wake capabilities
  - Instantly Available PC technology
  - Wake from USB (S1 and S3 only)
  - Power Management Event signal (PME#) wake-up support
  - WAKE# signal wake-up support
  - Wake from PS/2 device
  - Wake from serial port

1.12.1 ACPI

ACPI gives the operating system direct control over the power management and Plug and Play functions of a computer. The use of ACPI with the board requires an operating system that provides full ACPI support. ACPI features include:

- Plug and Play (including bus and device enumeration)
- Power management control of individual devices, add-in boards (some add-in boards may require an ACPI-aware driver), video displays, and hard disk drives
- Methods for achieving less than 15-watt system operation in the power-on/standby sleeping state
- A Soft-off feature that enables the operating system to power-off the computer
- Support for multiple wake-up events (see Table 8 on page 31)
- Support for a front panel power and sleep mode switch

Table 6 lists the system states based on how long the power switch is pressed, depending on how ACPI is configured with an ACPI-aware operating system.

Table 6. Effects of Pressing the Power Switch

If the system is in this state…	…and the power switch is pressed for	…the system enters this state
Off (ACPI G2/G5 – Soft off)	Less than four seconds	Power-on (ACPI G0 – working state)
On (ACPI G0 – working state)	Less than four seconds	Soft-off/Standby (ACPI G1 – sleeping state)
On (ACPI G0 – working state)	More than four seconds	Fail safe power-off (ACPI G2/G5 – Soft off)
Sleep (ACPI G1 – sleeping state)	Less than four seconds	Wake-up (ACPI G0 – working state)
Sleep (ACPI G1 – sleeping state)	More than four seconds	Power-off (ACPI G2/G5 – Soft off)

1.12.1.1 System States and Power States

Under ACPI, the operating system directs all system and device power state transitions. The operating system puts devices in and out of low-power states based on user preferences and knowledge of how devices are being used by applications. Devices that are not being used can be turned off. The operating system uses information from applications and user settings to put the system as a whole into a low-power state.

Table 7 lists the power states supported by the board along with the associated system power targets. See the ACPI specification for a complete description of the various system and power states.

Table 7. Power States and Targeted System Power

Global States	Sleeping States	Processor States	Device States	Targeted System Power (Note 1)
G0 – working state	S0 – working	C0 – working	D0 – working state.	Full power > 50 W
G0 – idle state	S0 – idle state	C3 – sleep	D0	Full power < 50 W
G0 – idle state	S0 – idle state	C4 – deep sleep	D0	Full power < 50 W
G1 – sleeping state	S1 – Processor stopped	C1 – stop grant	D1, D2, D3 – device specification specific.	5 W < power < 50 W
G1 – sleeping state	S3 – Suspend to RAM. Context saved to RAM.	No power	D3 – no power except for wake-up logic.	Power < 4.7 W (Note 2)
G1 – sleeping state	S4 – Suspend to disk. Context saved to disk.	No power	D3 – no power except for wake-up logic.	Power < 2.7 W (Note 2)
G2/S5	S5 – Soft off. Context not saved. Cold boot is required.	No power	D3 – no power except for wake-up logic.	Power < 2.7 W (Note 2)
G3 – mechanical off. AC power is disconnected from the computer.	No power to the system.	No power	D3 – no power for wake-up logic, except when provided by battery or external source.	No power to the system. Service can be performed safely.

Notes:

1. Total system power is dependent on the system configuration, including add-in boards and peripherals powered by the system chassis' power supply.
2. Dependent on the standby power consumption of wake-up devices used in the system inclusive of Wake on LAN allowance of 0.7 W. Intel Management Engine Interface (Intel MEI) is assumed to be in Wake on LAN mode.

1.12.1.2 Wake-up Devices and Events

Table 8 lists the devices or specific events that can wake the computer from specific states.

Table 8. Wake-up Devices and Events

These devices/events can wake up the computer…	…from this state
LAN	S1, S3, S4, S5
PME# signal	S1, S3, S4, S5
Power switch	S1, S3, S4, S5
RTC alarm	S1, S3, S4, S5
Serial port	S1, S3
USB	S1, S3
WAKE# signal	S1, S3, S4, S5
PS/2 port	S1, S3, S4, S5

Notes:

- S4 implies operating system support only.
- USB ports are turned off during S4/S5 states.
- The PCI Express WAKE# signal is controlled by the enable/disable option in the BIOS.

NOTE

The use of these wake-up events from an ACPI state requires an operating system that provides full ACPI support. In addition, software, drivers, and peripherals must fully support ACPI wake events.

1.12.2 Hardware Support

⚠ CAUTION

Ensure that the power supply provides adequate +5 V standby current if LAN wake capabilities and Instantly Available PC technology features are used. Failure to do so can damage the power supply. The total amount of standby current required depends on the wake devices supported and manufacturing options.

The board provides several power management hardware features, including:

- Power connector
- Fan headers
- LAN wake capabilities
- Instantly Available PC technology
- Wake from USB (S1 and S3 only)
- Power Management Event signal (PME#) wake-up support
- WAKE# signal wake-up support
- Wake from PS/2 devices
- Wake from serial port

LAN wake capabilities and Instantly Available PC technology require power from the +5 V standby line.

NOTE

The use of Wake from USB technologies from an ACPI state requires an operating system that provides full ACPI support.

1.12.2.1 Power Connector

ATX12V-compliant power supplies can turn off the system power through system control. When an ACPI-enabled system receives the correct command, the power supply removes all non-standby voltages.

When resuming from an AC power failure, the computer returns to the power state it was in before power was interrupted (on or off). The computer's response can be set using the Last Power State feature in the BIOS Setup program's Boot menu.

For information about	Refer to
The location of the main power connector	Figure 10, page 42
The signal names of the main power connector	Table 21, page 47

1.12.2.2 Fan Headers

The function/operation of the fan headers is as follows:

- The fans are on when the board is in the S0 state.
- The fans are off when the board is off or in the S3, S4, or S5 state.
- The processor fan header is wired to a fan tachometer input. The front and rear fan headers each have independent tachometer input to the hardware monitoring and fan control device. All fan headers support closed-loop fan control that can adjust the fan speed according to thermal conditions.
- All fan headers have a +12 V DC connection.
- The system fan headers support auto-detection for 4-pin and 3-pin system fans. If a 4-pin system fan is detected, PWM control is used. If a 3-pin fan is detected, linear voltage control is used.

For information about	Refer to
The locations of the fan headers and thermal sensors	Figure 6, page 28
The signal names of the fan headers	Table 18, page 46

1.12.2.3 LAN Wake Capabilities

⚠ CAUTION

For LAN wake capabilities, the +5 V standby line from the power supply must be capable of providing adequate +5 V standby current. Failure to provide adequate standby current when implementing LAN wake capabilities can damage the power supply.

LAN wake capabilities enable remote wake-up of the computer through a network. The LAN subsystem PCI bus network adapter monitors network traffic at the Media Independent Interface. Upon detecting a Magic Packet* frame, the LAN subsystem asserts a wake-up signal that powers up the computer. Depending on the LAN implementation, the board supports LAN wake capabilities with ACPI in the following ways:

- The PCI Express WAKE# signal
- The PCI bus PME# signal for PCI 2.3 compliant LAN designs
  - By Ping
  - Magic Packet
- The onboard LAN subsystem

1.12.2.4 Instantly Available PC Technology

CAUTION

For Instantly Available PC technology, the +5 V standby line from the power supply must be capable of providing adequate +5 V standby current. Failure to provide adequate standby current when implementing Instantly Available PC technology can damage the power supply.

Instantly Available PC technology enables the board to enter the ACPI S3 (Suspend-to-RAM) sleep-state. While in the S3 sleep-state, the computer will appear to be off (the power supply is off, and the front panel LED is amber if dual colored, or off if single colored.) When signaled by a wake-up device or event, the system quickly returns to its last known wake state. Table 8 on page 31 lists the devices and events that can wake the computer from the S3 state.

The board supports the *PCI Bus Power Management Interface Specification*. Add-in boards that also support this specification can participate in power management and can be used to wake the computer.

The use of Instantly Available PC technology requires operating system support and PCI 2.3 compliant add-in cards and drivers.

1.12.2.5 Wake from USB

USB bus activity wakes the computer from ACPI S1 or S3 state.

NOTE

Wake from USB requires the use of a USB peripheral that supports Wake from USB and support in the operating system.

1.12.2.6 PME# Signal Wake-up Support

When the PME# signal on the PCI bus is asserted, the computer wakes from an ACPI S1, S3, S4, or S5 state (with Wake on PME enabled in the BIOS).

1.12.2.7 WAKE# Signal Wake-up Support

When the WAKE# signal on the PCI Express bus is asserted, the computer wakes from an ACPI S1, S3, S4, or S5 state.

1.12.2.8 Wake from PS/2 Devices

PS/2 device activity wakes the computer from an ACPI S1, S3, S4, or S5 state. When the computer is in an S4 state, any key can be used to wake the computer provided a supported operating system is installed. When the computer is in the S5 state, the only PS/2 activity that will wake the computer is the either the alt-PrtScrn key combination or the "Power" key that is available on some keyboards. The BIOS can be used to toggle between either of the key combinations.

1.12.2.9 Wake from Serial Port

Serial port activity wakes the computer from an ACPI S1 or S3 state.

1.12.2.10 +5 V Standby Power Indicator LED

The +5 V standby power indicator LED shows that power is still present even when the computer appears to be off. Figure 7 shows the location of the standby power indicator LED.

CAUTION

If AC power has been switched off and the standby power indicator is still lit, disconnect the power cord before installing or removing any devices connected to the board. Failure to do so could damage the board and any attached devices.

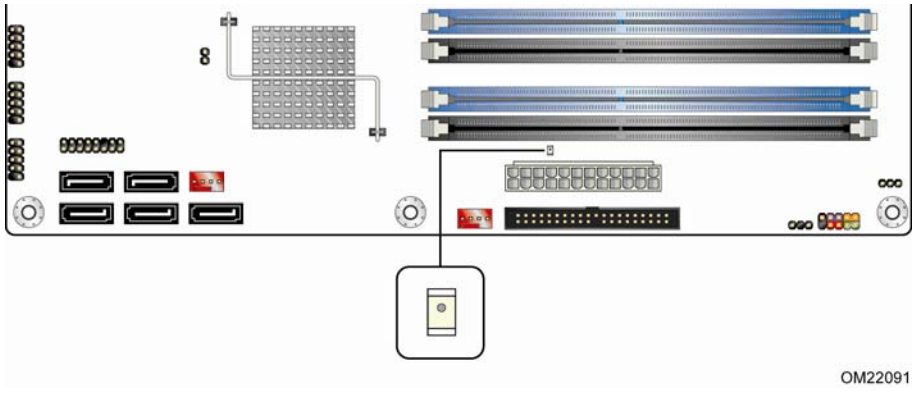


Figure 7. Location of the Standby Power Indicator LED

1.12.3 ENERGY STAR* 5.0, e-Standby, and ErP Compliance

The US Department of Energy and the US Environmental Protection Agency have continually revised the ENERGY STAR requirements. Intel has worked directly with these two governmental agencies in the definition of new requirements.

Intel Desktop Board DP43BF meets the following program requirements in an adequate system configuration, including appropriate selection of an efficient power supply:

- Energy Star v5.0, category B
- EPEAT*
- Korea e-Standby
- European Union Energy-related Products Directive 2009 (ErP)

For information about	Refer to
ENERGY STAR requirements and recommended configurations	http://www.intel.com/go/energystar
Electronic Product Environmental Assessment Tool (EPEAT)	http://www.epeat.net/
Korea e-Standby Program	http://www.kemco.or.kr/new_eng/pg02/pg02100300.asp
European Union Energy-related Products Directive 2009 (ErP)	http://ec.europa.eu/enterprise/policies/sustainable-business/sustainable-product-policy/ecodesign/index_en.htm

2 Technical Reference

2.1 Memory Map

2.1.1 Addressable Memory

The board utilizes 8 GB of addressable system memory. Typically the address space that is allocated for Conventional PCI bus add-in cards, PCI Express configuration space, BIOS (SPI Flash), and chipset overhead resides above the top of DRAM (total system memory). On a system that has 8 GB of system memory installed, it is not possible to use all of the installed memory due to system address space being allocated for other system critical functions. These functions include the following:

- BIOS/ SPI Flash (32 Mb)
- Local APIC (19 MB)
- Direct Media Interface (40 MB)
- Front side bus interrupts (17 MB)
- PCI Express configuration space (256 MB)
- MCH base address registers, internal graphics ranges, PCI Express ports (up to 512 MB)
- Memory-mapped I/O that is dynamically allocated for Conventional PCI and PCI Express add-in cards
- Base graphics memory support (1 MB or 8 MB)
- Intel MEI single channel (8 MB) or dual channel (16 MB)

The amount of installed memory that can be used will vary based on add-in cards, BIOS settings, and operating system installed. Figure 8 shows a schematic of the system memory map. All installed system memory can be used when there is no overlap of system addresses.

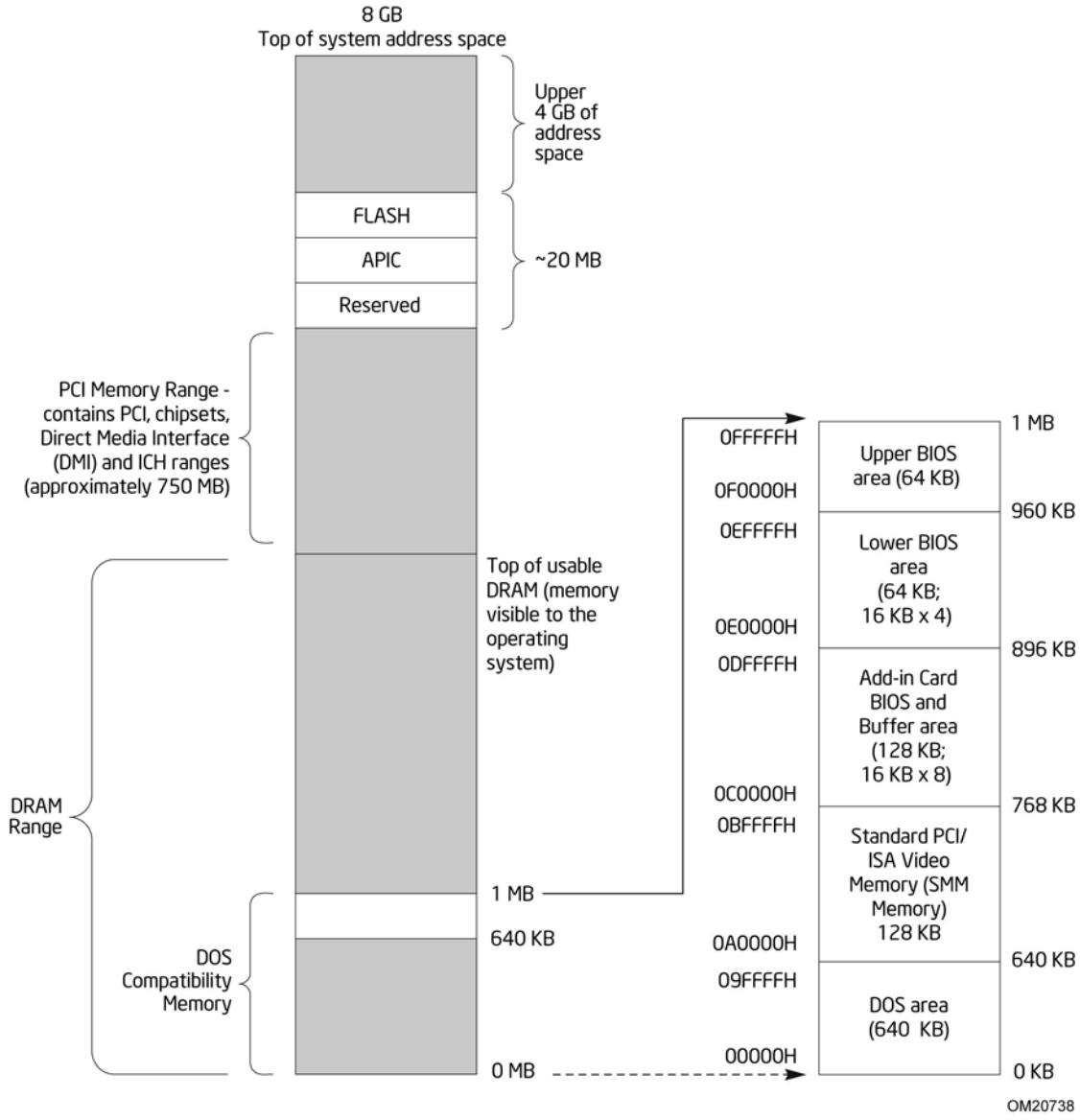


Figure 8. Detailed System Memory Address Map

Table 9 lists the system memory map.

Table 9. System Memory Map

Address Range (decimal)	Address Range (hex)	Size	Description
1024 K - 8388608 K	100000 - 3FFFFFFFF	8191 MB	Extended memory
960 K - 1024 K	F0000 - FFFFF	64 KB	Runtime BIOS
896 K - 960 K	E0000 - EFFFF	64 KB	Reserved
800 K - 896 K	C8000 - DFFFF	96 KB	Potential available high DOS memory (open to the Conventional PCI bus). Dependent on video adapter used.
640 K - 800 K	A0000 - C7FFF	160 KB	Video memory and BIOS
639 K - 640 K	9FC00 - 9FFFF	1 KB	Extended BIOS data (movable by memory manager software)
512 K - 639 K	80000 - 9FBFF	127 KB	Extended conventional memory
0 K - 512 K	00000 - 7FFFF	512 KB	Conventional memory

2.2 Connectors and Headers

CAUTION

Only the following connectors have overcurrent protection: Back panel and front panel USB, PS/2, and IEEE 1394a.

The other internal connectors/headers are not overcurrent protected and should connect only to devices inside the computer's chassis, such as fans and internal peripherals. Do not use these connectors/headers to power devices external to the computer's chassis. A fault in the load presented by the external devices could cause damage to the computer, the power cable, and the external devices themselves.

Furthermore, improper connection of USB or IEEE 1394 header single wire connectors may eventually overload the overcurrent protection and cause damage to the board.

NOTE

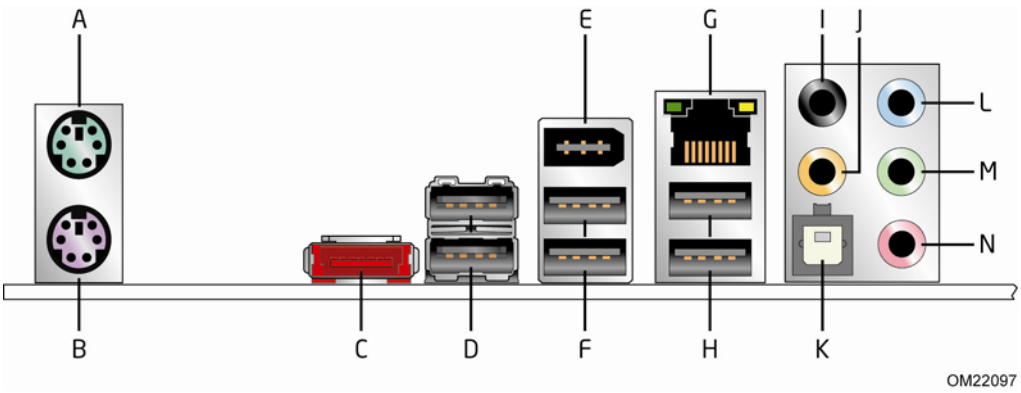
Computer systems that have an unshielded cable attached to a USB port may not meet FCC Class B requirements, even if no device is attached to the cable. Use a shielded cable that meets the requirements for full-speed devices.

This section describes the board's connectors and headers. The connectors and headers can be divided into these groups:

- Back panel I/O connectors (see page 41)
- Component-side connectors and headers (see page 42)

2.2.1 Back Panel Connectors

Figure 9 shows the location of the back panel connectors.



Item	Description
A	PS/2 keyboard/mouse port
B	PS/2 keyboard/mouse port
C	eSATA connector
D	USB ports (2)
E	IEEE 1394a connector
F	USB ports (2)
G	LAN
H	USB ports (2)
I	Rear surround
J	Center channel and LFE (subwoofer) audio out
K	S/PDIF digital audio out (optical)
L	Headphones/line in/side surround
M	Headphones/front speaker
N	Mic in

Figure 9. Back Panel Connectors

NOTES

The back panel audio line out connector is designed to power headphones or amplified speakers only. Poor audio quality occurs if passive (non-amplified) speakers are connected to this output.

2.2.2 Component-side Connectors and Headers

Figure 10 shows the locations of the component-side connectors and headers.

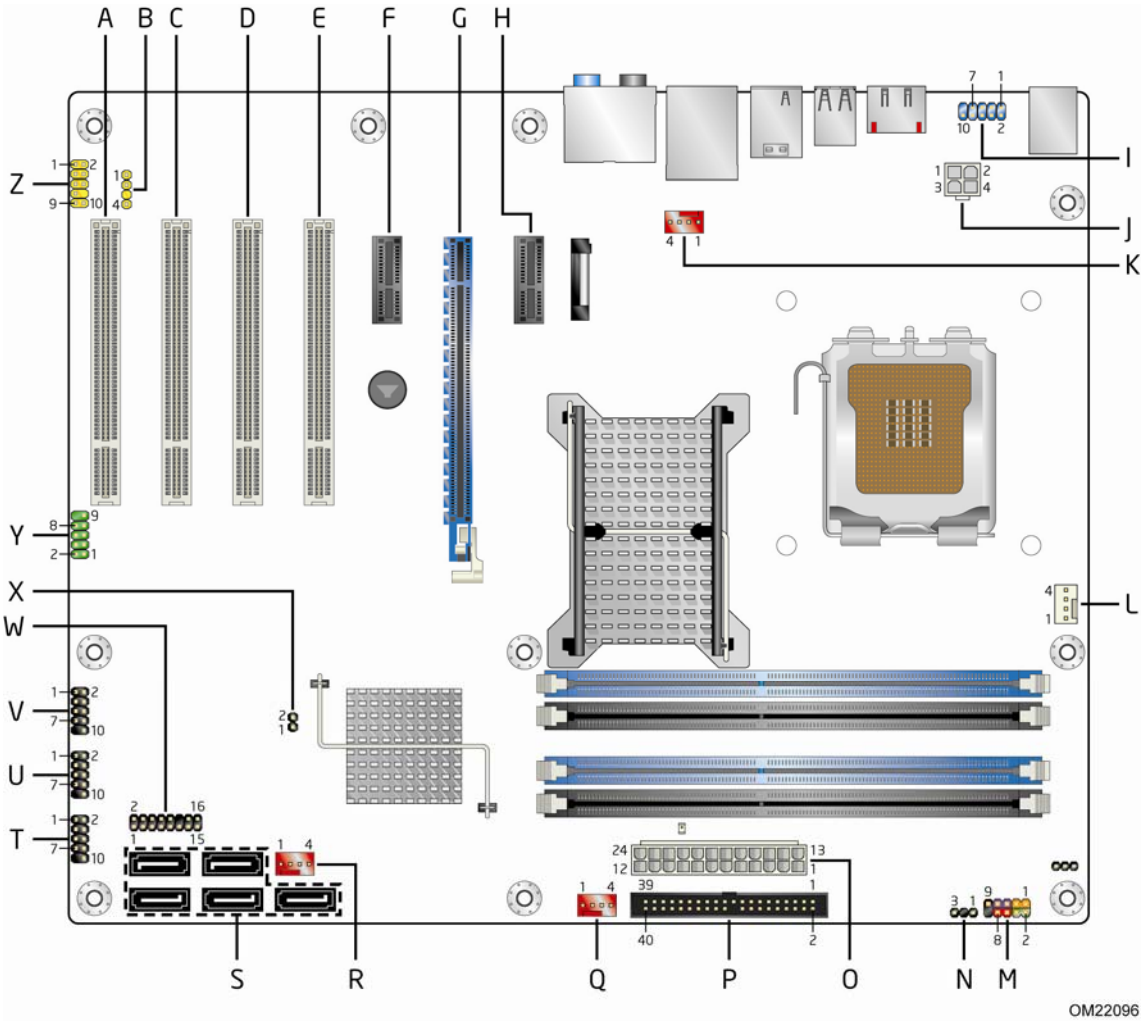


Figure 10. Component-side Connectors and Headers

Table 10 lists the component-side connectors and headers identified in Figure 10.

Table 10. Component-side Connectors and Headers Shown in Figure 10

Item/callout from Figure 10	Description
A	Conventional PCI bus add-in card connector
B	S/PDIF header
C	Conventional PCI bus add-in card connector
D	Conventional PCI bus add-in card connector
E	Conventional PCI bus add-in card connector
F	PCI Express x1 connector
G	PCI Express x16 connector
H	PCI Express x1 connector
I	Front panel IEEE 1394a header
J	Processor core power connector (2 x 2)
K	Rear chassis fan header
L	Processor fan header
M	Front panel header
N	Alternate front panel Power LED header
O	Main power connector (2 x 12)
P	Parallel ATA connector
Q	Front chassis fan header
R	Auxiliary chassis fan header
S	Serial ATA connectors (5)
T	Front panel USB header
U	Front panel USB header
V	Front panel USB header
W	Intel High Definition Audio Link header
X	Chassis intrusion header
Y	Serial port header
Z	Front panel audio header

2.2.2.1 Signal Tables for the Connectors and Headers

Table 11. Front Panel Audio Header for HD Audio

Pin	Signal Name	Pin	Signal Name
1	[Port 1] Left channel	2	Ground
3	[Port 1] Right channel	4	PRESENCE# (Dongle present)
5	[Port 2] Right channel	6	[Port 1] SENSE_RETURN
7	SENSE_SEND (Jack detection)	8	Key (no pin)
9	[Port 2] Left channel	10	[Port 2] SENSE_RETURN

Table 12. Front Panel Audio Header for AC '97 Audio

Pin	Signal Name	Pin	Signal Name
1	MIC	2	AUD_GND
3	MIC_BIAS	4	AUD_GND
5	FP_OUT_R	6	FP_RETURN_R
7	N/A	8	Key (no pin)
9	FP_OUT_L	10	FP_RETURN_L

Table 13. Serial ATA Connectors

Pin	Signal Name
1	Ground
2	TXP
3	TXN
4	Ground
5	RXN
6	RXP
7	Ground

Table 14. Serial Port Header

Pin	Signal Name	Pin	Signal Name
1	DCD (Data Carrier Detect)	2	RXD# (Receive Data)
3	TXD# (Transmit Data)	4	DTR (Data Terminal Ready)
5	Ground	6	DSR (Data Set Ready)
7	RTS (Request to Send)	8	CTS (Clear to Send)
9	RI (Ring Indicator)	10	Key (no pin)

Table 15. PATA Connector (44-Pin)

Pin	Signal Name	Pin	Signal Name
1	#Reset	2	GND
3	Data 7	4	Data 8
5	Data 6	6	Data 9
7	Data 5	8	Data 10
9	Data 4	10	Data 11
11	Data 3	12	Data 12
13	Data 2	14	Data 13
15	Data 1	16	Data 14
17	Data 0	18	Data 15
19	GND	20	Key (no pin)
21	DMA Request	22	GND
23	#IOW	24	GND
25	#IOR	26	GND
27	IO Chrdy	28	Cable Select
29	DMA Acknowledge	30	GND
31	IRQ14	32	#IOCS16
33	Addr 1	34	Passed Diagnostics
35	Addr 0	36	Addr 2
37	#CS0 (1F0-1F7)	38	#CS1 (3f6-3f7)
39	#Active (LED driver)	40	GND
41	+5V_DC (logic)	42	+5V_DC (motor)
43	GND	44	Type (GND = ATA)

Table 16. S/PDIF Header

Pin	Signal Name
1	Ground
2	S/PDIF out
3	Key (no pin)
4	+5 VDC

Table 17. Chassis Intrusion Header

Pin	Signal Name
1	Intruder#
2	Ground

Table 18. Processor (4-Pin) Fan Header

Pin	Signal Name
1	Ground
2	+12 V
3	FAN_TACH
4	FAN_CONTROL

Table 19. Front, Rear, and Auxiliary Chassis Fan Headers

Pin	4-Wire Support	Pin	3-Wire Support
1	Ground	3	Ground
2	+12 V	2	FAN_POWER
3	FAN_TACH	1	FAN_TACH
4	FAN_CONTROL	N/A	N/A

2.2.2.2 Add-in Card Connectors

The board has the following add-in card connectors:

- PCI Express 2.0 x16: one PCI Express 2.0 x16 connector supporting simultaneous transfer speeds up to 8 GB/s of peak bandwidth per direction and up to 16 GB/s concurrent bandwidth.
- PCI Express 1.1 x1: two PCI Express 1.1 x1 connectors. The x1 interface supports simultaneous transfer speeds up to 250 MB/s of peak bandwidth per direction and up to 2 GB/s concurrent bandwidth.
- Conventional PCI (rev 2.3 compliant) bus: four Conventional PCI bus add-in card connectors.

Note the following considerations for the Conventional PCI bus connectors:

- The Conventional PCI bus connectors are bus master capable.
- SMBus signals are routed to the Conventional PCI bus connectors. This enables Conventional PCI bus add-in boards with SMBus support to access sensor data on the desktop board. The specific SMBus signals are as follows:
  - The SMBus clock line is connected to pin A40.
  - The SMBus data line is connected to pin A41.

2.2.2.3 Power Supply Connectors

The board has the following power supply connectors:

- **Main power** – a 2 x 12 connector. This connector is compatible with 2 x 10 connectors previously used on Intel Desktop boards. The board supports the use of ATX12V power supplies with either 2 x 10 or 2 x 12 main power cables. When using a power supply with a 2 x 10 main power cable, attach that cable on the rightmost pins of the main power connector, leaving pins 11, 12, 23, and 24 unconnected.
- **Processor core power** – a 2 x 2 connector. This connector provides power directly to the processor voltage regulator and must always be used. Failure to do so will prevent the board from booting.

Table 20. Processor Core Power Connector

Pin	Signal Name	Pin	Signal Name
1	Ground	2	Ground
3	+12 V	4	+12 V

Table 21. Main Power Connector

Pin	Signal Name	Pin	Signal Name
1	+3.3 V	13	+3.3 V
2	+3.3 V	14	-12 V
3	Ground	15	Ground
4	+5 V	16	PS-ON# (power supply remote on/off)
5	Ground	17	Ground
6	+5 V	18	Ground
7	Ground	19	Ground
8	PWRGD (Power Good)	20	No connect
9	+5 V (Standby)	21	+5 V
10	+12 V	22	+5 V
11	+12 V (Note)	23	+5 V (Note)
12	2 x 12 connector detect (Note)	24	Ground (Note)

Note: When using a 2 x 10 power supply cable, this pin will be unconnected.

For information about	Refer to
Power supply considerations	Section 2.5.1, page 54

2.2.2.4 Front Panel Header

This section describes the functions of the front panel header. Table 22 lists the signal names of the front panel header. Figure 11 is a connection diagram for the front panel header.

Table 22. Front Panel Header

Pin	Signal	In/ Out	Description	Pin	Signal	In/ Out	Description
Hard Drive Activity LED				**Power LED**			
1	HD_PWR	Out	Hard disk LED pull-up to +5 V	2	HDR_BLNK_GRN	Out	Front panel green LED
3	HDA#	Out	Hard disk active LED	4	HDR_BLNK_YEL	Out	Front panel yellow LED
Reset Switch				**On/Off Switch**			
5	Ground		Ground	6	FPBUT_IN	In	Power switch
7	FP_RESET#	In	Reset switch	8	Ground		Ground
Power				**Not Connected**			
9	+5 V		Power	10	N/C		Not connected

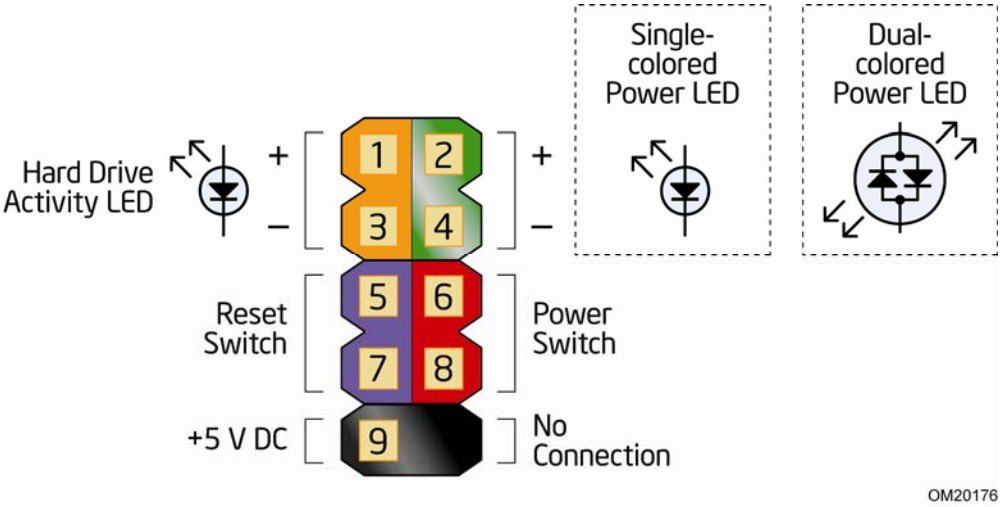


Figure 11. Connection Diagram for Front Panel Header

2.2.2.4.1 Hard Drive Activity LED Header

Pins 1 and 3 can be connected to an LED to provide a visual indicator that data is being read from or written to a hard drive. Proper LED function requires one of the following:

- A Serial ATA hard drive connected to an onboard Serial ATA connector
- A Parallel ATA hard drive connected to an onboard Parallel ATA connector

2.2.2.4.2 Reset Switch Header

Pins 5 and 7 can be connected to a momentary single pole, single throw (SPST) type switch that is normally open. When the switch is closed, the board resets and runs the POST.

2.2.2.4.3 Power/Sleep LED Header

Pins 2 and 4 can be connected to a one- or two-color LED. Table 23 shows the possible states for a one-color LED. Table 24 shows the possible states for a two-color LED.

Table 23. States for a One-Color Power LED

LED State	Description
Off	Power off/sleeping
Steady Green	Running

Table 24. States for a Two-Color Power LED

LED State	Description
Off	Power off
Steady Green	Running
Steady Yellow	Sleeping

NOTE

The colors listed in Table 23 and Table 24 are suggested colors only. Actual LED colors are chassis-specific.

2.2.2.4.4 Power Switch Header

Pins 6 and 8 can be connected to a front panel momentary-contact power switch. The switch must pull the SW_ON# pin to ground for at least 50 ms to signal the power supply to switch on or off. (The time requirement is due to internal debounce circuitry on the board.) At least two seconds must pass before the power supply will recognize another on/off signal.

2.2.2.5 Alternate Front Panel Power LED Header

Pins 1 and 3 of this header duplicate the signals on pins 2 and 4 of the front panel header.

Table 25. Alternate Front Panel Power LED Header

Pin	Signal Name	In/Out	Description
1	HDR_BLNK_GRN	Out	Front panel green LED
2	Not connected		
3	HDR_BLNK_YEL	Out	Front panel yellow LED

2.2.2.6 Front Panel USB Headers

Figure 12 is a connection diagram for the front panel USB headers.

NOTE

- *The +5 V DC power on the USB headers is fused.*
- *Use only a front panel USB connector that conforms to the USB 2.0 specification for high-speed USB devices.*

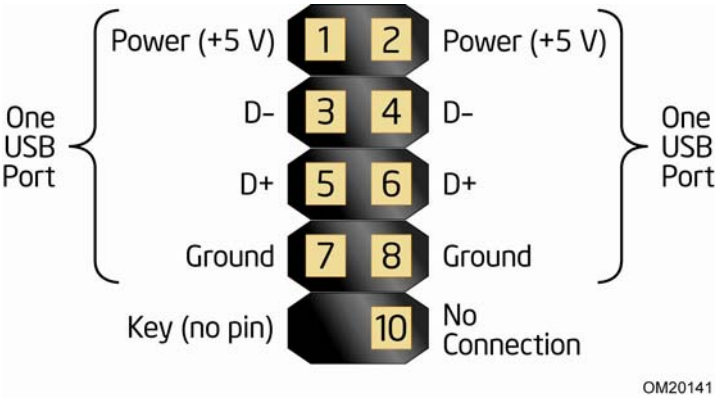


Figure 12. Connection Diagram for Front Panel USB Headers

2.2.2.7 Front Panel IEEE 1394a Header

Figure 13 is a connection diagram for the IEEE 1394a header.

NOTE

- *The +12 V DC power on the IEEE 1394a header is fused.*
- *The IEEE 1394a header provides one IEEE 1394a port.*

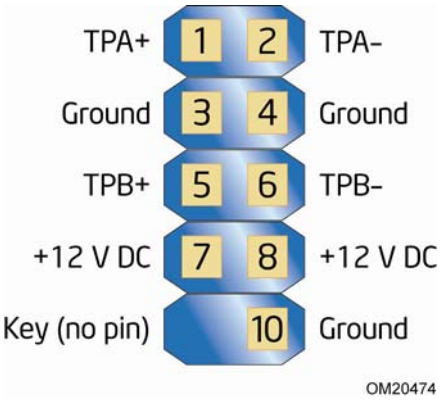


Figure 13. Connection Diagram for IEEE 1394a Header

2.3 BIOS Configuration Jumper Block

CAUTION

Do not move the jumper with the power on. Always turn off the power and unplug the power cord from the computer before changing a jumper setting. Otherwise, the board could be damaged.

Figure 14 shows the location of the BIOS configuration jumper block. The jumper determines the BIOS Setup program's mode. Table 26 lists the jumper settings for the three modes: normal, configure, and recovery. When the jumper is set to configure mode and the computer is powered-up, the BIOS compares the processor version and the microcode version in the BIOS and reports if the two match.

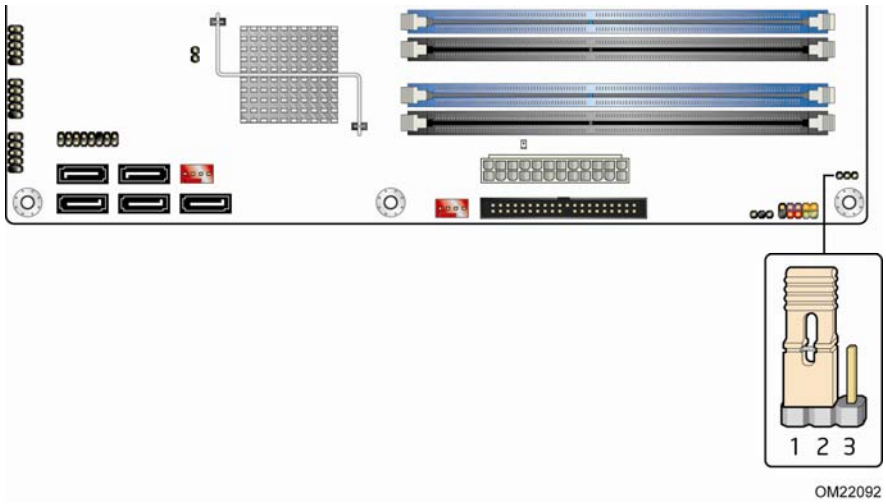
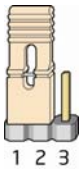
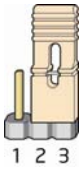


Figure 14. Location of the BIOS Configuration Jumper Block

Table 26. BIOS Setup Configuration Jumper Settings

Function/Mode	Jumper Setting		Configuration
Normal	1-2		The BIOS uses current configuration information and passwords for booting.
Configure	2-3		After the POST runs, Setup runs automatically. The maintenance menu is displayed.
Recovery	None		The BIOS attempts to recover the BIOS configuration. See Section 3.7 for more information on BIOS recovery.

2.4 Mechanical Considerations

2.4.1 Form Factor

The board is designed to fit into an ATX-form-factor chassis. Figure 15 illustrates the mechanical form factor for the board. Dimensions are given in inches [millimeters]. The outer dimensions are 9.60 inches by 11.60 inches [243.84 millimeters by 294.64 millimeters]. Location of the I/O connectors and mounting holes are in compliance with the ATX specification.

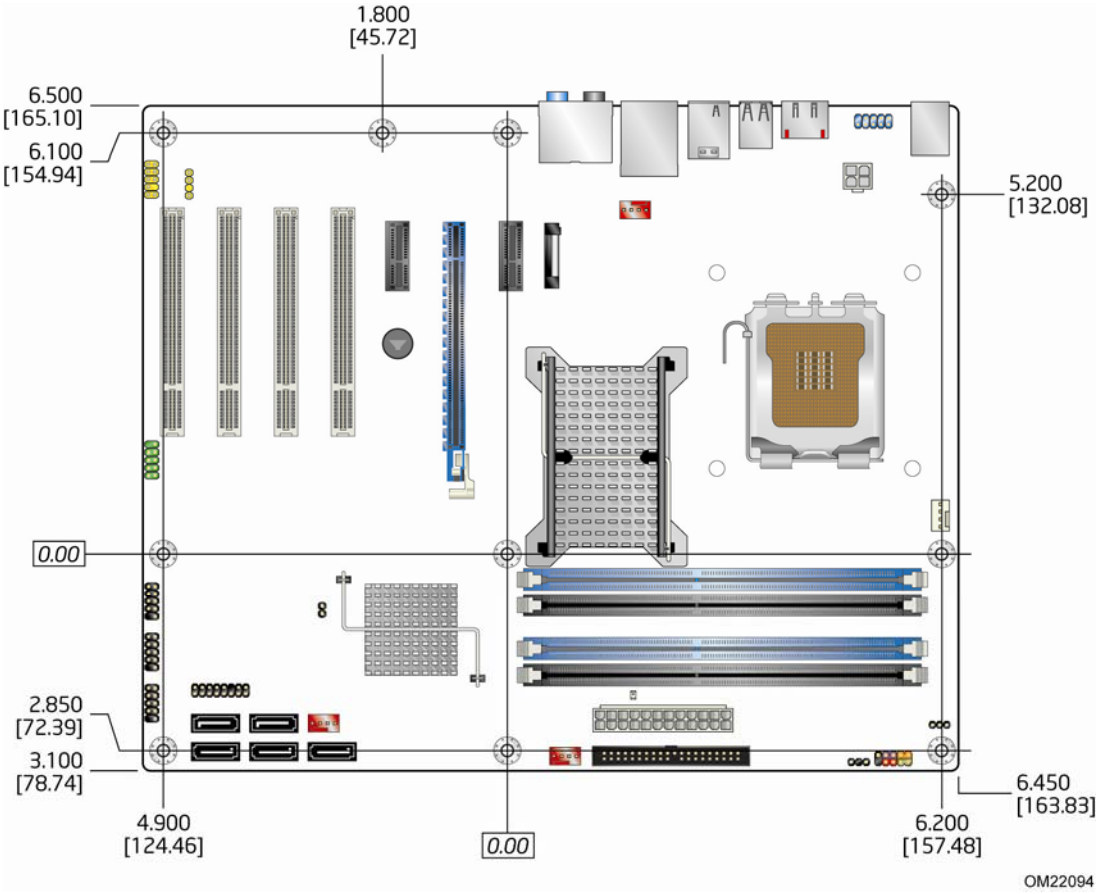


Figure 15. Board Dimensions

2.5 Electrical Considerations

2.5.1 Power Supply Considerations

⚠ CAUTION

The +5 V standby line from the power supply must be capable of providing adequate +5 V standby current. Failure to do so can damage the power supply. The total amount of standby current required depends on the wake devices supported and manufacturing options.

Additional power required will depend on configurations chosen by the integrator.

The power supply must comply with the indicated parameters of the ATX form factor specification.

- The potential relation between 3.3 VDC and +5 VDC power rails
- The current capability of the +5 VSB line
- All timing parameters
- All voltage tolerances

For example, for a system consisting of a supported 65 W processor (see Section 1.4 on page 15 for a list of supported processors), 1 GB DDR2 RAM, one hard disk drive, one optical drive, and all board peripherals enabled, the minimum recommended power supply is 135W. Table 27 lists the recommended power supply current values.

Table 27. Recommended Power Supply Current Values

Output Voltage	3.3 V	5 V	12 V1	12 V2	-12 V	5 VSB
Current	2.38 A	3.17 A	5.92 A	2.95 A	0.04 A	0.64 A

2.5.2 Fan Header Current Capability

⚠ CAUTION

The processor fan must be connected to the processor fan header, not to a chassis fan header. Connecting the processor fan to a chassis fan header may result in onboard component damage that will halt fan operation.

Table 28 lists the current capability of the fan headers.

Table 28. Fan Header Current Capability

Fan Header	**Maximum Available Current**
Processor fan	2.0 A
Front chassis fan	1.5 A
Rear chassis fan	1.5 A
Auxiliary chassis fan	1.5 A

2.5.3 Add-in Board Considerations

The board is designed to provide 2 A (average) of +5 V current for each add-in board. The total +5 V current draw for add-in boards for a fully loaded board (all three expansion slots filled) must not exceed 8 A.

2.6 Thermal Considerations

CAUTION

A chassis with a maximum internal ambient temperature of 38 °C at the processor fan inlet is a requirement. Use a processor heat sink that provides omni-directional airflow to maintain required airflow across the processor voltage regulator area.

CAUTION

Failure to ensure appropriate airflow may result in reduced performance of both the processor and/or voltage regulator or, in some instances, damage to the board. For a list of chassis that have been tested with Intel desktop boards please refer to the following website:

http://www3.intel.com/cd/channel/reseller/asmo-na/eng/tech_reference/53211.htm

All responsibility for determining the adequacy of any thermal or system design remains solely with the reader. Intel makes no warranties or representations that merely following the instructions presented in this document will result in a system with adequate thermal performance.

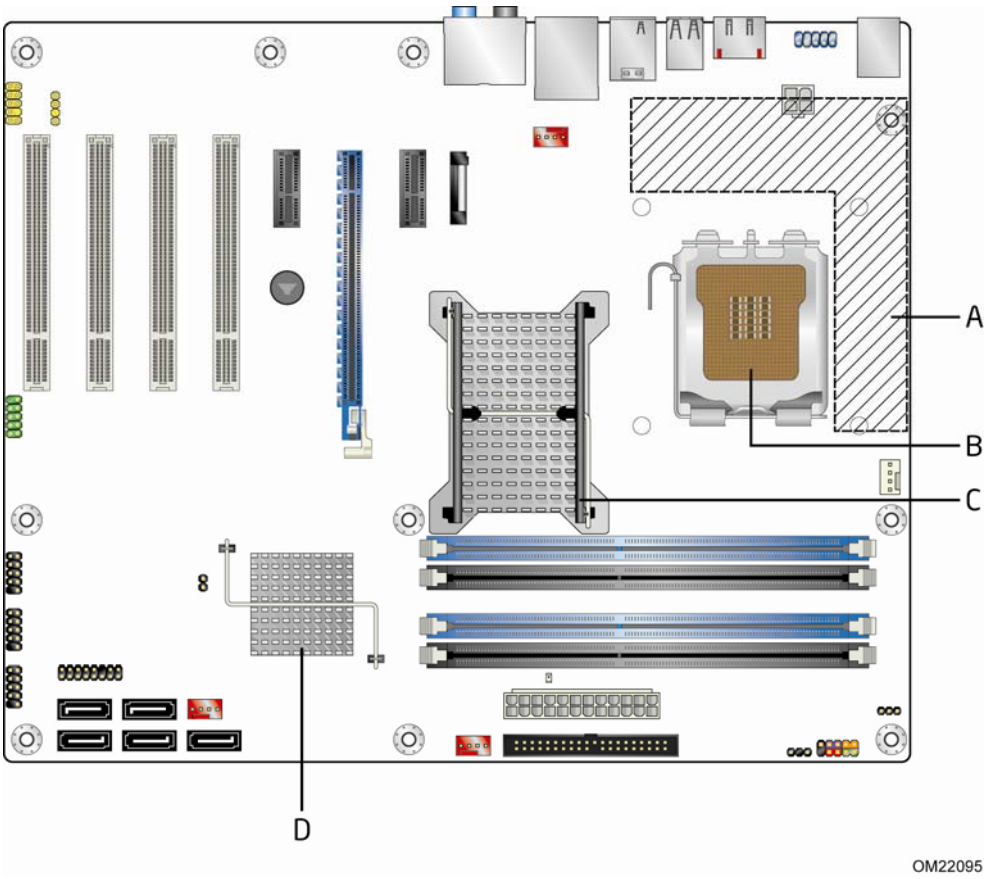
CAUTION

Ensure that the ambient temperature does not exceed the board's maximum operating temperature. Failure to do so could cause components to exceed their maximum case temperature and malfunction. For information about the maximum operating temperature, see the environmental specifications in Section 2.8.

CAUTION

Ensure that proper airflow is maintained in the processor voltage regulator circuit. Failure to do so may result in damage to the voltage regulator circuit. The processor voltage regulator area (shown in Figure 16) can reach a temperature of up to 85 °C in an open chassis.

Figure 16 shows the locations of the localized high temperature zones.



Item	Description
A	Processor voltage regulator area
B	Processor
C	Intel 82P43 MCH
D	Intel 82801JIR (Intel ICH10R)

Figure 16. Localized High Temperature Zones

Table 29 provides maximum case temperatures for the board components that are sensitive to thermal changes. The operating temperature, current load, or operating frequency could affect case temperatures. Maximum case temperatures are important when considering proper airflow to cool the board.

Table 29. Thermal Considerations for Components

Component	Maximum Case Temperature
Processor	For processor case temperature, see processor datasheets and processor specification updates
Intel 82P43 MCH	103 °C (under bias)
Intel 82801JIR (Intel ICH10R)	112 °C (under bias)

For information about	Refer to
Processor datasheets and specification updates	Section 1.2, page 14
Intel P43 Express chipset datasheets, specification updates, and design guides	http://www.intel.com/products/chipsets/index.htm

2.7 Reliability

The Mean Time Between Failures (MTBF) prediction is calculated using component and subassembly random failure rates. The calculation is based on the Telcordia SR-332, Method I Case 1 50% electrical stress, 40 ºC ambient. The MTBF prediction is used to estimate repair rates and spare parts requirements.

The MTBF data is calculated from predicted data at 40 ºC. The Intel Desktop Board DP43BF MTBF is 426,167.42 hours.

2.8 Environmental

Table 30 lists the environmental specifications for the board.

Table 30. Intel Desktop Board DP43BF Environmental Specifications

Parameter	Specification		
Temperature			
Non-Operating	-20 °C to +70 °C at 95% humidity		
Operating	0 °C to +50 °C at 90% humidity		
Shock			
Unpackaged	50 g trapezoidal waveform		
	Velocity change of 170 inches/second²		
Packaged	Half sine 2 millisecond		
	Product weight (pounds)	Free fall (inches)	Velocity change (inches/second²)
	<20	36	167
	21-40	30	152
	41-80	24	136
	81-100	18	118
Vibration			
Unpackaged	5 Hz to 20 Hz: 0.01 g² Hz sloping up to 0.02 g² Hz		
	20 Hz to 500 Hz: 0.02 g² Hz (flat)		
Packaged	10 Hz to 40 Hz: 0.015 g² Hz (flat)		
	40 Hz to 500 Hz: 0.015 g² Hz sloping down to 0.00015 g² Hz		

3 Overview of BIOS Features

3.1 Introduction

The board uses an Intel BIOS that is stored in the Serial Peripheral Interface Flash Memory (SPI Flash) and can be updated using a disk-based program. The SPI Flash contains the BIOS Setup program, POST, the PCI auto-configuration utility, LAN EEPROM information, and Plug and Play support.

The BIOS displays a message during POST identifying the type of BIOS and a revision code. The initial production BIOSs are identified as RKG4310H.86A.

When the BIOS Setup configuration jumper is set to configure mode and the computer is powered-up, the BIOS compares the CPU version and the microcode version in the BIOS and reports if the two match.

The BIOS Setup program can be used to view and change the BIOS settings for the computer. The BIOS Setup program is accessed by pressing the <F2> key after the Power-On Self-Test (POST) memory test begins and before the operating system boot begins. The menu bar is shown below.

Maintenance	Main	Advanced	Security	Power	Boot	Exit

NOTE

The maintenance menu is displayed only when the board is in configure mode. Section 2.3 on page 52 shows how to put the board in configure mode.

Table 31 lists the BIOS Setup program menu features.

Table 31. BIOS Setup Program Menu Bar

Maintenance	Main	Advanced	Security	Power	Boot	Exit
Clears passwords and displays processor information	Displays processor and memory configuration	Configures advanced features available through the chipset	Sets passwords and security features	Configures power management features and power supply controls	Selects boot options	Saves or discards changes to Setup program options

Table 32 lists the function keys available for menu screens.

Table 32. BIOS Setup Program Function Keys

BIOS Setup Program Function Key	Description
<←> or <→>	Selects a different menu screen (Moves the cursor left or right)
<↑> or <↓>	Selects an item (Moves the cursor up or down)
<Tab>	Selects a field (Not implemented)
<Enter>	Executes command or selects the submenu
<F9>	Load the default configuration values for the current menu
<F10>	Save the current values and exits the BIOS Setup program
<Esc>	Exits the menu

3.2 BIOS Flash Memory Organization

The Serial Peripheral Interface Flash Memory (SPI Flash) includes a 32 Mb (4096 KB) flash memory device.

3.3 Resource Configuration

3.3.1 PCI* Autoconfiguration

The BIOS can automatically configure PCI devices. PCI devices may be onboard or add-in cards. Autoconfiguration lets a user insert or remove PCI cards without having to configure the system. When a user turns on the system after adding a PCI card, the BIOS automatically configures interrupts, the I/O space, and other system resources. Any interrupts set to Available in Setup are considered to be available for use by the add-in card.

3.4 System Management BIOS (SMBIOS)

SMBIOS is a Desktop Management Interface (DMI) compliant method for managing computers in a managed network.

The main component of SMBIOS is the Management Information Format (MIF) database, which contains information about the computing system and its components. Using SMBIOS, a system administrator can obtain the system types, capabilities, operational status, and installation dates for system components. The MIF database defines the data and provides the method for accessing this information. The BIOS enables applications such as third-party management software to use SMBIOS. The BIOS stores and reports the following SMBIOS information:

- BIOS data, such as the BIOS revision level
- Fixed-system data, such as peripherals, serial numbers, and asset tags
- Resource data, such as memory size, cache size, and processor speed
- Dynamic data, such as event detection and error logging

Non-Plug and Play operating systems require an additional interface for obtaining the SMBIOS information. The BIOS supports an SMBIOS table interface for such operating systems. Using this support, an SMBIOS service-level application running on a non-Plug and Play operating system can obtain the SMBIOS information. Additional board information can be found in the BIOS under the Additional Information header under the Main BIOS page.

3.5 Legacy USB Support

Legacy USB support enables USB devices to be used even when the operating system's USB drivers are not yet available. Legacy USB support is used to access the BIOS Setup program, and to install an operating system that supports USB. By default, Legacy USB support is set to Enabled.

Legacy USB support operates as follows:

1. When you apply power to the computer, legacy support is disabled.
2. POST begins.
3. Legacy USB support is enabled by the BIOS allowing you to use a USB keyboard to enter and configure the BIOS Setup program and the maintenance menu.
4. POST completes.
5. The operating system loads. While the operating system is loading, USB keyboards and mice are recognized and may be used to configure the operating system. (Keyboards and mice are not recognized during this period if Legacy USB support was set to Disabled in the BIOS Setup program.)
6. After the operating system loads the USB drivers, all legacy and non-legacy USB devices are recognized by the operating system, and Legacy USB support from the BIOS is no longer used.
7. Additional USB legacy feature options can be access by using Intel® Integrator Toolkit.

To install an operating system that supports USB, verify that Legacy USB support in the BIOS Setup program is set to Enabled and follow the operating system's installation instructions.

3.6 BIOS Updates

The BIOS can be updated using either of the following utilities, which are available on the Intel World Wide Web site:

- Intel® Express BIOS Update utility, which enables automated updating while in the Windows environment. Using this utility, the BIOS can be updated from a file on a hard disk, a USB drive (a flash drive or a USB drive), or an optical drive.
- Intel® Flash Memory Update Utility, which requires booting from DOS. Using this utility, the BIOS can be updated from a file on a hard disk, a USB drive (a flash drive or a USB drive), or an optical drive.

Both utilities verify that the updated BIOS matches the target system to prevent accidentally installing an incompatible BIOS.

NOTE

Review the instructions distributed with the upgrade utility before attempting a BIOS update.

For information about	Refer to
BIOS update utilities	http://support.intel.com/support/motherboards/desktop/sb/CS-022312.htm.

3.6.1 Language Support

The BIOS Setup program and help messages are supported in US English. Check the Intel web site for details.

3.6.2 Custom Splash Screen

During POST, an Intel® splash screen is displayed by default. This splash screen can be augmented with a custom splash screen. The Intel Integrator's Toolkit or Intel® Integrator Assistant that are available from Intel can be used to create a custom splash screen.

NOTE

If you add a custom splash screen, it will share space with the Intel branded logo.

For information about	Refer to
Intel Integrator Toolkit	http://developer.intel.com/design/motherbd/software/itk/
Additional Intel® software tools	http://developer.intel.com/products/motherboard/DP43BF/tools.htm and http://developer.intel.com/design/motherbd/software.htm

3.7 BIOS Recovery

It is unlikely that anything will interrupt a BIOS update; however, if an interruption occurs, the BIOS could be damaged. Table 33 lists the drives and media types that can and cannot be used for BIOS recovery. The BIOS recovery media does not need to be made bootable.

Table 33. Acceptable Drives/Media Types for BIOS Recovery

Media Type	Can be used for BIOS recovery?
Optical drive connected to the Serial ATA interface	Yes
USB removable drive (a USB Flash Drive, for example)	Yes
USB diskette drive (with a 1.44 MB diskette)	No
USB hard disk drive	No
Legacy diskette drive (with a 1.44 MB diskette) connected to the legacy diskette drive interface	No

For information about	Refer to
BIOS recovery	http://support.intel.com/support/motherboards/desktop/sb/CS-023360.htm

3.8 Boot Options

In the BIOS Setup program, the user can choose to boot from a hard drive, optical drive, removable drive, or the network. The default setting is for the optical drive to be the first boot device, the hard drive second, removable drive third, and the network fourth.

3.8.1 Optical Drive Boot

Booting from the optical drive is supported in compliance to the El Torito bootable CD-ROM format specification. Under the Boot menu in the BIOS Setup program, the optical drive is listed as a boot device. Boot devices are defined in priority order. Accordingly, if there is not a bootable CD in the optical drive, the system will attempt to boot from the next defined drive.

3.8.2 Network Boot

The network can be selected as a boot device. This selection allows booting from the onboard LAN or a network add-in card with a remote boot ROM installed.

Pressing the <F12> key during POST automatically forces booting from the LAN. To use this key during POST, the User Access Level in the BIOS Setup program's Security menu must be set to Full.

3.8.3 Booting Without Attached Devices

For use in embedded applications, the BIOS has been designed so that, after passing the POST, the operating system loader is invoked even if the following devices are not present:

- Video adapter
- Keyboard
- Mouse

3.8.4 Changing the Default Boot Device During POST

Pressing the <F10> key during POST causes a boot device menu to be displayed. This menu displays the list of available boot devices (as set in the BIOS setup program's Boot Device Priority Submenu). Table 34 lists the boot device menu options.

Table 34. Boot Device Menu Options

Boot Device Menu Function Keys	Description
<↑> or <↓>	Selects a default boot device
<Enter>	Exits the menu, saves changes, and boots from the selected device
<Esc>	Exits the menu without saving changes

3.9 Adjusting Boot Speed

These factors affect system boot speed:

- Selecting and configuring peripherals properly
- Optimized BIOS boot parameters

3.9.1 Peripheral Selection and Configuration

The following techniques help improve system boot speed:

- Choose a hard drive with parameters such as "power-up to data ready" in less than eight seconds that minimizes hard drive startup delays.
- Select an optical drive with a fast initialization rate. This rate can influence POST execution time.
- Eliminate unnecessary add-in adapter features, such as logo displays, screen repaints, or mode changes in POST. These features may add time to the boot process.
- Try different monitors. Some monitors initialize and communicate with the BIOS more quickly, which enables the system to boot more quickly.

3.9.2 BIOS Boot Optimizations

Use of the following BIOS Setup program settings reduces the POST execution time.

- In the Boot Menu, set the hard disk drive as the first boot device. As a result, the POST does not first seek a diskette drive, which saves about one second from the POST execution time.
- In the Peripheral Configuration submenu, disable the LAN device if it will not be used. This can reduce up to four seconds of option ROM boot time.

NOTE

It is possible to optimize the boot process to the point where the system boots so quickly that the Intel logo screen (or a custom logo splash screen) will not be seen. Monitors and hard disk drives with minimum initialization times can also contribute to a boot time that might be so fast that necessary logo screens and POST messages cannot be seen.

This boot time may be so fast that some drives might be not be initialized at all. If this condition should occur, it is possible to introduce a programmable delay ranging from three to 30 seconds (using the Hard Disk Pre-Delay feature of the Advanced Menu in the Drive Configuration Submenu of the BIOS Setup program).

3.10 BIOS Security Features

The BIOS includes security features that restrict access to the BIOS Setup program and who can boot the computer. A supervisor password and a user password can be set for the BIOS Setup program and for booting the computer, with the following restrictions:

- The supervisor password gives unrestricted access to view and change all the Setup options in the BIOS Setup program. This is the supervisor mode.
- The user password gives restricted access to view and change Setup options in the BIOS Setup program. This is the user mode.
- If only the supervisor password is set, pressing the <Enter> key at the password prompt of the BIOS Setup program allows the user restricted access to Setup.
- If both the supervisor and user passwords are set, users can enter either the supervisor password or the user password to access Setup. Users have access to Setup respective to which password is entered.
- Setting the user password restricts who can boot the computer. The password prompt will be displayed before the computer is booted. If only the supervisor password is set, the computer boots without asking for a password. If both passwords are set, the user can enter either password to boot the computer.
- For enhanced security, use different passwords for the supervisor and user passwords.
- Valid password characters are A-Z, a-z, and 0-9. Passwords may be up to 16 characters in length.

Table 35 shows the effects of setting the supervisor password and user password. This table is for reference only and is not displayed on the screen.

Table 35. Supervisor and User Password Functions

Password Set	Supervisor Mode	User Mode	Setup Options	Password to Enter Setup	Password During Boot
Neither	Can change all options (Note)	Can change all options (Note)	None	None	None
Supervisor only	Can change all options	Can change a limited number of options	Supervisor Password	Supervisor	None
User only	N/A	Can change all options	Enter Password Clear User Password	User	User
Supervisor and user set	Can change all options	Can change a limited number of options	Supervisor Password Enter Password	Supervisor or user	Supervisor or user

Note: If no password is set, any user can change all Setup options.

4 Error Messages and Beep Codes

4.1 Speaker

The board-mounted speaker provides audible error code (beep code) information during POST.

For information about	Refer to
The location of the onboard speaker	Figure 1, page 11

4.2 BIOS Beep Codes

Whenever a recoverable error occurs during POST, the BIOS causes the board's speaker to beep an error message describing the problem (see Table 36).

Table 36. BIOS Beep Codes

Type	Pattern	Frequency
Processor initialization complete	One 0.5 second beep when the CPU initialization process completes.	3270 Hz
POST complete	One 0.5 second beep when POST completes.	3270 Hz
BIOS update in progress	None	
Video error	On-off (0.5 seconds each) two times, then 3.0 second pause (off), entire pattern repeats (beeps and pause) until the system is powered off.	3270 Hz When no VGA option ROM is found.
Memory error	On-off (0.5 seconds each) three times, then 3.0 second pause (off), entire pattern repeats (beeps and pause) until the system is powered off.	1280 Hz
Thermal trip warning	On-off (0.5 seconds each) four times, then 3.0 second pause (off), entire pattern repeats (beeps and pause) until the sixteenth beep, then ends.	1280 Hz

4.3 Front-panel Power LED Blink Codes

Whenever a recoverable error occurs during POST, the BIOS causes the board's front panel power LED to blink an error message describing the problem (see Table 37).

Table 37. Front-panel Power LED Blink Codes

Type	Pattern	Note
Processor initialization complete	On when the system powers up, then off for 0.5 seconds.	
POST complete	On when the system powers up, then off for 0.5 seconds.	
BIOS update in progress	Off when the update begins, then on for 0.5 seconds, then off for 0.5 seconds. The pattern repeats until the BIOS update is complete.	
Video error	On-off (0.5 seconds each) two times, then 3.0 second pause (off), entire pattern repeats (blink and pause) until the system is powered off.	When no VGA option ROM is found.
Memory error	On-off (0.5 seconds each) three times, then 3.0 second pause (off), entire pattern repeats (blinks and pause) until the system is powered off.	
Thermal trip warning	On-off (0.5 seconds each) four times, then 3.0 second pause (off), entire pattern repeats (blinks and pause) until the sixteenth blink, then ends.	

4.4 BIOS Error Messages

Whenever a recoverable error occurs during POST, the BIOS displays an error message describing the problem. Table 38 lists the error messages and provides a brief description of each.

Table 38. BIOS Error Messages

Error Message	Explanation
CMOS Battery Low	The battery may be losing power. Replace the battery soon.
CMOS Checksum Bad	The CMOS checksum is incorrect. CMOS memory may have been corrupted. Run Setup to reset values.
Memory Size Decreased	Memory size has decreased since the last boot. If no memory was removed, then memory may be bad.
No Boot Device Available	System did not find a device to boot.

4.5 Port 80h POST Codes

During the POST, the BIOS generates diagnostic progress codes (POST codes) to I/O port 80h. If the POST fails, execution stops and the last POST code generated is left at port 80h. This code is useful for determining the point where an error occurred.

Displaying the POST codes requires a PCI bus add-in card, often called a POST card. The POST card can decode the port and display the contents on a medium such as a seven-segment display.

NOTE

The POST card must be installed in PCI bus connector 1.

The following tables provide information about the POST codes generated by the BIOS:

- Table 39 lists the Port 80h POST code ranges
- Table 40 lists the Port 80h POST codes themselves
- Table 41 lists the Port 80h POST sequence

NOTE

In the tables listed above, all POST codes and range values are listed in hexadecimal.

Table 39. Port 80h POST Code Ranges

Range	Category/Subsystem
00 – 0F	Debug codes: Can be used by any PEIM/driver for debug.
10 – 1F	Host Processors: 1F is an unrecoverable CPU error.
20 – 2F	Memory/Chipset: 2F is no memory detected or no useful memory detected.
30 – 3F	Recovery: 3F indicated recovery failure.
40 – 4F	Reserved for future use.
50 – 5F	I/O Busses: PCI, USB, ISA, ATA, etc. 5F is an unrecoverable error. Start with PCI.
60 – 6F	Reserved for future use (for new busses).
70 – 7F	Output Devices: All output consoles. 7F is an unrecoverable error.
80 – 8F	Reserved for future use (new output console codes).
90 – 9F	Input devices: Keyboard/Mouse. 9F is an unrecoverable error.
A0 – AF	Reserved for future use (new input console codes).
B0 – BF	Boot Devices: Includes fixed media and removable media. BF is an unrecoverable error.
C0 – CF	Reserved for future use.
D0 – DF	Boot device selection.
E0 – FF	E0 – EE: Miscellaneous codes. See Table 40. EF: Boot/S3 resume failure. F0 – FF: FF processor exception.

Table 40. Port 80h POST Codes

POST Code	Description of POST Operation
	Host Processor
10	Power-on initialization of the host processor (Boot Strap Processor)
11	Host processor cache initialization (including APs)
12	Starting Application processor initialization
13	SMM initialization
	Chipset
21	Initializing a chipset component
	Memory
22	Reading SPD from memory DIMMs
23	Detecting presence of memory DIMMs
24	Programming timing parameters in the memory controller and the DIMMs
25	Configuring memory
26	Optimizing memory settings
27	Initializing memory, such as ECC init
28	Testing memory
	PCI Bus
50	Enumerating PCI busses
51	Allocating resources to PCI bus
52	Hot Plug PCI controller initialization
53 – 57	Reserved for PCI Bus
	USB
58	Resetting USB bus
59	Reserved for USB
	ATA/ATAPI/SATA
5A	Resetting PATA/SATA bus and all devices
5B	Reserved for ATA
	SMBus
5C	Resetting SMBus
5D	Reserved for SMBus
	Local Console
70	Resetting the VGA controller
71	Disabling the VGA controller
72	Enabling the VGA controller
	Remote Console
78	Resetting the console controller
79	Disabling the console controller
7A	Enabling the console controller

continued

Table 40. Port 80h POST Codes (continued)

POST Code	Description of POST Operation
	Keyboard (PS/2 or USB)
90	Resetting keyboard
91	Disabling keyboard
92	Detecting presence of keyboard
93	Enabling the keyboard
94	Clearing keyboard input buffer
95	Instructing keyboard controller to run Self Test (PS/2 only)
	Mouse (PS/2 or USB)
98	Resetting mouse
99	Disabling mouse
9A	Detecting presence of mouse
9B	Enabling mouse
	Fixed Media
B0	Resetting fixed media
B1	Disabling fixed media
B2	Detecting presence of a fixed media (IDE hard drive detection etc.)
B3	Enabling/configuring a fixed media
	Removable Media
B8	Resetting removable media
B9	Disabling removable media
BA	Detecting presence of a removable media (IDE, CD-ROM detection, etc.)
BC	Enabling/configuring a removable media
	BDS
D*y*	Trying boot selection y (y=0 to 15)
	PEI Core
E0	Started dispatching PEIMs (emitted on first report of EFI_SW_PC_INIT_BEGIN EFI_SW_PEI_PC_HANDOFF_TO_NEXT)
E2	Permanent memory found
E1, E3	Reserved for PEI/PEIMs
	DXE Core
E4	Entered DXE phase
E5	Started dispatching drivers
E6	Started connecting drivers

continued

Table 40. Port 80h POST Codes (continued)

POST Code	Description of POST Operation
	DXE Drivers
E7	Waiting for user input
E8	Checking password
E9	Entering BIOS setup
EB	Calling Legacy Option ROMs
	Runtime Phase/EFI OS Boot
F4	Entering Sleep state
F5	Exiting Sleep state
F8	EFI boot service ExitBootServices ( ) has been called
F9	EFI runtime service SetVirtualAddressMap ( ) has been called
FA	EFI runtime service ResetSystem ( ) has been called
	PEIMs/Recovery
30	Crisis Recovery has initiated per user request
31	Crisis Recovery has initiated by software (corrupt flash)
34	Loading recovery capsule
35	Handing off control to the recovery capsule
3F	Unable to recover

Table 41. Typical Port 80h POST Sequence

POST Code	Description
21	Initializing a chipset component
22	Reading SPD from memory DIMMs
23	Detecting presence of memory DIMMs
25	Configuring memory
28	Testing memory
34	Loading recovery capsule
E4	Entered DXE phase
12	Starting application processor initialization
13	SMM initialization
50	Enumerating PCI busses
51	Allocating resourced to PCI bus
92	Detecting the presence of the keyboard
90	Resetting keyboard
94	Clearing keyboard input buffer
95	Keyboard Self Test
EB	Calling Video BIOS
58	Resetting USB bus
5A	Resetting PATA/SATA bus and all devices
92	Detecting the presence of the keyboard
90	Resetting keyboard
94	Clearing keyboard input buffer
5A	Resetting PATA/SATA bus and all devices
28	Testing memory
90	Resetting keyboard
94	Clearing keyboard input buffer
E7	Waiting for user input
01	INT 19
00	Ready to boot

5 Regulatory Compliance and Battery Disposal Information

5.1 Regulatory Compliance

This section contains the following regulatory compliance information for Intel Desktop Board DP43BF:

- Safety standards
- European Union Declaration of Conformity statement
- Product Ecology statements
- Electromagnetic Compatibility (EMC) standards
- Product certification markings

5.1.1 Safety Standards

Intel Desktop Board DP43BF complies with the safety standards stated in Table 42 when correctly installed in a compatible host system.

Table 42. Safety Standards

Standard	Title
CSA/UL 60950-1, First Edition	Information Technology Equipment – Safety - Part 1: General Requirements (USA and Canada)
EN 60950-1:2006, Second Edition	Information Technology Equipment – Safety - Part 1: General Requirements (European Union)
IEC 60950-1:2005, Second Edition	Information Technology Equipment – Safety - Part 1: General Requirements (International)

5.1.2 European Union Declaration of Conformity Statement

We, Intel Corporation, declare under our sole responsibility that the product Intel® Desktop Board DP43BF is in conformity with all applicable essential requirements necessary for CE marking, following the provisions of the European Council Directive 2004/108/EC (EMC Directive) and 2006/95/EC (Low Voltage Directive).

The product is properly CE marked demonstrating this conformity and is for distribution within all member states of the EU with no restrictions.

This product follows the provisions of the European Directives 2004/108/EC and 2006/95/EC.

Čeština Tento výrobek odpovídá požadavkům evropských směrnic 2004/108/EC a 2006/95/EC.

Dansk Dette produkt er i overensstemmelse med det europæiske direktiv 2004/108/EC & 2006/95/EC.

Dutch Dit product is in navolging van de bepalingen van Europees Directief 2004/108/EC & 2006/95/EC.

Eesti Antud toode vastab Euroopa direktiivides 2004/108/EC ja 2006/95/EC kehtestatud nõuetele.

Suomi Tämä tuote noudattaa EU-direktiivin 2004/108/EC & 2006/95/EC määräyksiä.

Français Ce produit est conforme aux exigences de la Directive Européenne 2004/108/EC & 2006/95/EC.

Deutsch Dieses Produkt entspricht den Bestimmungen der Europäischen Richtlinie 2004/108/EC & 2006/95/EC.

Ελληνικά Το παρόν προϊόν ακολουθεί τις διατάξεις των Ευρωπαϊκών Οδηγιών 2004/108/EC και 2006/95/EC.

Magyar E termék megfelel a 2004/108/EC és 2006/95/EC Európai Irányelv előírásainak.

Icelandic Þessi vara stenst reglugerð Evrópska Efnahags Bandalagsins númer 2004/108/EC & 2006/95/EC.

Italiano Questo prodotto è conforme alla Direttiva Europea 2004/108/EC & 2006/95/EC.

Latviešu Šis produkts atbilst Eiropas Direktīvu 2004/108/EC un 2006/95/EC noteikumiem.

Lietuvių Šis produktas atitinka Europos direktyvų 2004/108/EC ir 2006/95/EC nuostatas.

Malti Dan il-prodott hu konformi mal-provvedimenti tad-Direttivi Ewropej 2004/108/EC u 2006/95/EC.

Norsk Dette produktet er i henhold til bestemmelsene i det europeiske direktivet 2004/108/EC & 2006/95/EC.

Polski Niniejszy produkt jest zgodny z postanowieniami Dyrektyw Unii Europejskiej 2004/108/EC i 73/23/EWG.

Portuguese Este produto cumpre com as normas da Diretiva Européia 2004/108/EC & 2006/95/EC.

Español Este producto cumple con las normas del Directivo Europeo 2004/108/EC & 2006/95/EC.

Slovensky Tento produkt je v súlade s ustanoveniami európskych direktív 2004/108/EC a 2006/95/EC.

Slovenščina Izdelek je skladen z določbami evropskih direktiv 2004/108/EC in 2006/95/EC.

Svenska Denna produkt har tillverkats i enlighet med EG-direktiv 2004/108/EC & 2006/95/EC.

Türkçe Bu ürün, Avrupa Birliği'nin 2004/108/EC ve 2006/95/EC yönergelerine uyar.

5.1.3 Product Ecology Statements

The following information is provided to address worldwide product ecology concerns and regulations.

5.1.3.1 Disposal Considerations

This product contains the following materials that may be regulated upon disposal: lead solder on the printed wiring board assembly.

5.1.3.2 Recycling Considerations

As part of its commitment to environmental responsibility, Intel has implemented the Intel Product Recycling Program to allow retail consumers of Intel's branded products to return used products to selected locations for proper recycling.

Please consult the http://www.intel.com/intel/other/ehs/product_ecology for the details of this program, including the scope of covered products, available locations, shipping instructions, terms and conditions, etc.

中文

作为其对环境责任之承诺的部分，英特尔已实施 Intel Product Recycling Program（英特尔产品回收计划），以允许英特尔品牌产品的零售消费者将使用过的产品退还至指定地点作恰当的重复使用处理。

请参考http://www.intel.com/intel/other/ehs/product_ecology 了解此计划的详情，包括涉及产品之范围、回收地点、运送指导、条款和条件等。

Deutsch

Als Teil von Intels Engagement für den Umweltschutz hat das Unternehmen das Intel Produkt-Recyclingprogramm implementiert, das Einzelhandelskunden von Intel Markenprodukten ermöglicht, gebrauchte Produkte an ausgewählte Standorte für ordnungsgemäßes Recycling zurückzugeben.

Details zu diesem Programm, einschließlich der darin eingeschlossenen Produkte, verfügbaren Standorte, Versandanweisungen, Bedingungen usw., finden Sie auf der http://www.intel.com/intel/other/ehs/product_ecology

Español

Como parte de su compromiso de responsabilidad medioambiental, Intel ha implantado el programa de reciclaje de productos Intel, que permite que los consumidores al detalle de los productos Intel devuelvan los productos usados en los lugares seleccionados para su correspondiente reciclado.

Consulte la http://www.intel.com/intel/other/ehs/product_ecology para ver los detalles del programa, que incluye los productos que abarca, los lugares disponibles, instrucciones de envío, términos y condiciones, etc.

Français

Dans le cadre de son engagement pour la protection de l'environnement, Intel a mis en œuvre le programme Intel Product Recycling Program (Programme de recyclage des produits Intel) pour permettre aux consommateurs de produits Intel de recycler les produits usés en les retournant à des adresses spécifiées.

Visitez la page Web http://www.intel.com/intel/other/ehs/product_ecology pour en savoir plus sur ce programme, à savoir les produits concernés, les adresses disponibles, les instructions d'expédition, les conditions générales, etc.

日本語

インテルでは、環境保護活動の一環として、使い終えたインテル
ブランド製品を指定の場所へ返送していただき、リサイクルを適切に行えるよう、インテル製品リサイクル
プログラムを発足させました。

対象製品、返送先、返送方法、ご利用規約など、このプログラムの詳細情報は、http://www.intel.com/intel/other/ehs/product_ecology（英語）をご覧ください。

Malay

Sebagai sebahagian daripada komitmennya terhadap tanggungjawab persekitaran, Intel telah melaksanakan Program Kitar Semula Produk untuk membenarkan pengguna-pengguna runcit produk jenama Intel memulangkan produk terguna ke lokasi-lokasi terpilih untuk dikitarkan semula dengan betul.

Sila rujuk http://www.intel.com/intel/other/ehs/product_ecology untuk mendapatkan butir-butir program ini, termasuklah skop produk yang dirangkumi, lokasi-lokasi tersedia, arahan penghantaran, terma & syarat, dsb.

Portuguese

Como parte deste compromisso com o respeito ao ambiente, a Intel implementou o Programa de Reciclagem de Produtos para que os consumidores finais possam enviar produtos Intel usados para locais selecionados, onde esses produtos são reciclados de maneira adequada.

Consulte o site http://www.intel.com/intel/other/ehs/product_ecology (em Inglês) para obter os detalhes sobre este programa, inclusive o escopo dos produtos cobertos, os locais disponíveis, as instruções de envio, os termos e condições, etc.

Russian

В качестве части своих обязательств к окружающей среде, в Intel создана программа утилизации продукции Intel (Product Recycling Program) для предоставления конечным пользователям марок продукции Intel возможности возврата используемой продукции в специализированные пункты для должной утилизации.

Пожалуйста, обратитесь на веб-сайт http://www.intel.com/intel/other/ehs/product_ecology за информацией об этой программе, принимаемых продуктах, местах приема, инструкциях об отправке, положениях и условиях и т.д.

Türkçe

Intel, çevre sorumluluğuna bağımlılığının bir parçası olarak, perakende tüketicilerin Intel markalı kullanılmış ürünlerini belirlenmiş merkezlere iade edip uygun şekilde geri dönüştürmesini amaçlayan Intel Ürünleri Geri Dönüşüm Programı'nı uygulamaya koymuştur.

Bu programın ürün kapsamı, ürün iade merkezleri, nakliye talimatları, kayıtlar ve şartlar v.s dahil bütün ayrıntılarını ögrenmek için lütfen http://www.intel.com/intel/other/ehs/product_ecology

Web sayfasına gidin.

5.1.3.3 Lead Free Desktop Board

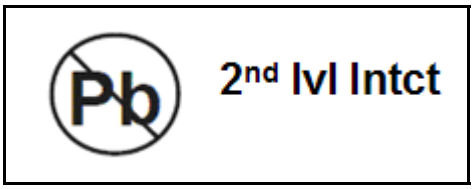
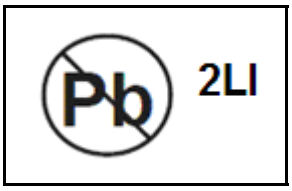
This Desktop Board is a European Union Restriction of Hazardous Substances (EU RoHS Directive 2002/95/EC) compliant product. EU RoHS restricts the use of six materials. One of the six restricted materials is lead.

This Desktop Board is lead free although certain discrete components used on the board contain a small amount of lead which is necessary for component performance and/or reliability. This Desktop Board is referred to as "Lead-free second level interconnect." The board substrate and the solder connections from the board to the components (second-level connections) are all lead free.

China bans the same substances and has the same limits as EU RoHS; however it requires different product marking and controlled substance information. The required mark shows the Environmental Friendly Usage Period (EFUP). The EFUP is defined as the number of years for which controlled listed substances will not leak or chemically deteriorate while in the product.

Table 43 shows the various forms of the "Lead-Free 2nd Level Interconnect" mark as it appears on the board and accompanying collateral.

Table 43. Lead-Free Board Markings

Description	Mark
Lead-Free 2nd Level Interconnect: This symbol is used to identify electrical and electronic assemblies and components in which the lead (Pb) concentration level in the desktop board substrate and the solder connections from the board to the components (second-level interconnect) is not greater than 0.1% by weight (1000 ppm).	 or  or 

5.1.4 EMC Regulations

Intel Desktop Board DP43BF complies with the EMC regulations stated in Table 44 when correctly installed in a compatible host system.

Table 44. EMC Regulations

Regulation	Title
FCC 47 CFR Part 15, Subpart B	Title 47 of the Code of Federal Regulations, Part15, Subpart B, Radio Frequency Devices. (USA)
ICES-003 Issue 4	Interference-Causing Equipment Standard, Digital Apparatus. (Canada)
EN55022:2006	Limits and methods of measurement of Radio Interference Characteristics of Information Technology Equipment. (European Union)
EN55024:1998	Information Technology Equipment – Immunity Characteristics Limits and methods of measurement. (European Union)
EN55022:2006	Australian Communications Authority, Standard for Electromagnetic Compatibility. (Australia and New Zealand)
CISPR 22:2005 +A1:2005 +A2:2006	Limits and methods of measurement of Radio Disturbance Characteristics of Information Technology Equipment. (International)
CISPR 24:1997 +A1:2001 +A2:2002	Information Technology Equipment – Immunity Characteristics – Limits and Methods of Measurement. (International)
VCCI V-3/2007.04, V-4/2007.04	Voluntary Control for Interference by Information Technology Equipment. (Japan)
KN-22, KN-24	Korean Communications Commission – Framework Act on Telecommunications and Radio Waves Act (South Korea)
CNS 13438:2006	Bureau of Standards, Metrology and Inspection (Taiwan)

Japanese Kanji statement translation: this is a Class B product based on the standard of the Voluntary Control Council for Interference from Information Technology Equipment (VCCI). If this is used near a radio or television receiver in a domestic environment, it may cause radio interference. Install and use the equipment according to the instruction manual.

この装置は、情報処理装置等電波障害自主規制協議会（ＶＣＣＩ）の基準に基づくクラスＢ情報技術装置です。この装置は、家庭環境で使用することを目的としていますが、この装置がラジオやテレビジョン受信機に近接して使用されると、受信障害を引き起こすことがあります。
取扱説明書に従って正しい取り扱いをして下さい。

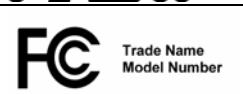
Korean Class B statement translation: this is household equipment that is certified to comply with EMC requirements. You may use this equipment in residential environments and other non-residential environments.

이 기기는 가정용으로 전자파적합등록을 한 기기로서
주거지역에서는 물론 모든 지역에서 사용할 수 있습니다.

5.1.5 Product Certification Markings (Board Level)

Intel Desktop Board DP43BF has the product certification markings shown in Table 45.

Table 45. Product Certification Markings

Description	Mark
UL joint US/Canada Recognized Component mark.	
FCC Declaration of Conformity logo mark for Class B equipment.	
CE mark. Declaring compliance to European Union (EU) EMC directive and Low Voltage directive.	
Australian Communications Authority (ACA) and New Zealand Radio Spectrum Management (NZ RSM) C-tick mark.	
Japan VCCI (Voluntary Control Council for Interference) mark.	
S. Korea KCC (Korean Communications Commission) mark.	
Taiwan BSMI (Bureau of Standards, Metrology and Inspections) mark.	
Printed wiring board manufacturer's recognition mark. Consists of a unique UL recognized manufacturer's logo, along with a flammability rating (solder side).	V-0
China RoHS/Environmentally Friendly Use Period Logo: This is an example of the symbol used on Intel Desktop Boards and associated collateral. The color of the mark may vary depending upon the application. The Environmental Friendly Usage Period (EFUP) for Intel Desktop Boards has been determined to be 10 years.	

5.2 Battery Disposal Information

CAUTION

Risk of explosion if the battery is replaced with an incorrect type. Batteries should be recycled where possible. Disposal of used batteries must be in accordance with local environmental regulations.

PRECAUTION

Risque d'explosion si la pile usagée est remplacée par une pile de type incorrect. Les piles usagées doivent être recyclées dans la mesure du possible. La mise au rebut des piles usagées doit respecter les réglementations locales en vigueur en matière de protection de l'environnement.

FORHOLDSREGEL

Eksplosionsfare, hvis batteriet erstattes med et batteri af en forkert type. Batterier bør om muligt genbruges. Bortskaffelse af brugte batterier bør foregå i overensstemmelse med gældende miljølovgivning.

OBS!

Det kan oppstå eksplosjonsfare hvis batteriet skiftes ut med feil type. Brukte batterier bør kastes i henhold til gjeldende miljølovgivning.

VIKTIGT!

Risk för explosion om batteriet ersätts med felaktig batterityp. Batterier ska kasseras enligt de lokala miljövårdsbestämmelserna.

VARO

Räjähdysvaara, jos pariston tyyppi on väärä. Paristot on kierrätettävä, jos se on mahdollista. Käytetyt paristot on hävitettävä paikallisten ympäristömääräysten mukaisesti.

VORSICHT

Bei falschem Einsetzen einer neuen Batterie besteht Explosionsgefahr. Die Batterie darf nur durch denselben oder einen entsprechenden, vom Hersteller empfohlenen Batterietyp ersetzt werden. Entsorgen Sie verbrauchte Batterien den Anweisungen des Herstellers entsprechend.

AVVERTIMENTO

Esiste il pericolo di un esplosione se la pila non viene sostituita in modo corretto. Utilizzare solo pile uguali o di tipo equivalente a quelle consigliate dal produttore. Per disfarsi delle pile usate, seguire le istruzioni del produttore.

PRECAUCIÓN

Existe peligro de explosión si la pila no se cambia de forma adecuada. Utilice solamente pilas iguales o del mismo tipo que las recomendadas por el fabricante del equipo. Para deshacerse de las pilas usadas, siga igualmente las instrucciones del fabricante.

WAARSCHUWING

Er bestaat ontploffingsgevaar als de batterij wordt vervangen door een onjuist type batterij. Batterijen moeten zoveel mogelijk worden gerecycled. Houd u bij het weggooien van gebruikte batterijen aan de plaatselijke milieuwetgeving.

ATENÇÃO

Haverá risco de explosão se a bateria for substituída por um tipo de bateria incorreto. As baterias devem ser recicladas nos locais apropriados. A eliminação de baterias usadas deve ser feita de acordo com as regulamentações ambientais da região.

AŚCIAROŽZNAŚĆ

Існуе рызыка выбуху, калі заменены акумулятар неправільнага тыпу. Акумулятары павінны, па магчымасці, перапрацоўвацца. Пазбаўляцца ад старых акумулятараў патрэбна згодна з мясцовым заканадаўствам па экалогіі.

UPOZORNÌNÍ

V případě výměny baterie za nesprávný druh může dojít k výbuchu. Je-li to možné, baterie by měly být recyklovány. Baterie je třeba zlikvidovat v souladu s místními předpisy o životním prostředí.

Προσοχή

Υπάρχει κίνδυνος για έκρηξη σε περίπτωση που η μπαταρία αντικατασταθεί από μία λανθασμένου τύπου. Οι μπαταρίες θα πρέπει να ανακυκλώνονται όταν κάτι τέτοιο είναι δυνατό. Η απόρριψη των χρησιμοποιημένων μπαταριών πρέπει να γίνεται σύμφωνα με τους κατά τόπο περιβαλλοντικούς κανονισμούς.

VIGYAZAT

Ha a telepet nem a megfelelő típusú telepre cseréli, az felrobbanhat. A telepeket lehetőség szerint újra kell hasznosítani. A használt telepeket a helyi környezetvédelmi előírásoknak megfelelően kell kiselejtezni.

注意

異なる種類の電池を使用すると、爆発の危険があります。リサイクル
が可能な地域であれば、電池をリサイクルしてください。使用後の電
池を破棄する際には、地域の環境規制に従ってください。

AWAS

Risiko letupan wujud jika bateri digantikan dengan jenis yang tidak betul. Bateri sepatutnya dikitar semula jika boleh. Pelupusan bateri terpakai mestilah mematuhi peraturan alam sekitar tempatan.

OSTRZEŻENIE

Istnieje niebezpieczeństwo wybuchu w przypadku zastosowania niewłaściwego typu baterii. Zużyte baterie należy w miarę możliwości utylizować zgodnie z odpowiednimi przepisami ochrony środowiska.

PRECAUȚIE

Risc de explozie, dacă bateria este înlocuită cu un tip de baterie necorespunzător. Bateriile trebuie reciclate, dacă este posibil. Depozitarea bateriilor uzate trebuie să respecte reglementările locale privind protecţia mediului.

ВНИМАНИЕ

При использовании батареи несоответствующего типа существует риск ее взрыва. Батареи должны быть утилизированы по возможности. Утилизация батарей должна проводится по правилам, соответствующим местным требованиям.

UPOZORNENIE

Ak batériu vymeníte za nesprávny typ, hrozí nebezpečenstvo jej výbuchu.
Batérie by sa mali podľa možnosti vždy recyklovať. Likvidácia použitých batérií sa musí vykonávať v súlade s miestnymi predpismi na ochranu životného prostredia.

POZOR

Zamenjava baterije z baterijo drugačnega tipa lahko povzroči eksplozijo.
Če je mogoče, baterije reciklirajte. Rabljene baterije zavrzite v skladu z lokalnimi okoljevarstvenimi predpisi.

คำเตือน

ระวังการระเบิดที่เกิดจากเปลี่ยนแบตเตอรี่ผิดประเภท หากเป็นไปได้ ควรนำแบตเตอรี่ไปรีไซเคิล การทิ้งแบตเตอรี่ใช้แล้วต้องเป็นไปตามกฎข้อบังคับด้านสิ่งแวดล้อมของท้องถิ่น.

UYARI

Yanlış türde pil takıldığında patlama riski vardır. Piller mümkün olduğunda geri dönüştürülmelidir. Kullanılmış piller, yerel çevre yasalarına uygun olarak atılmalıdır.

ОСТОРОГА

Використовуйте батареї правильного типу, інакше існуватиме ризик вибуху. Якщо можливо, використані батареї слід утилізувати. Утилізація використаних батарей має бути виконана згідно місцевих норм, що регулюють охорону довкілля.

UPOZORNĚNÍ

V případě výměny baterie za nesprávný druh může dojít k výbuchu. Je-li to možné, baterie by měly být recyklovány. Baterie je třeba zlikvidovat v souladu s místními předpisy o životním prostředí.

ETTEVAATUST

Kui patarei asendatakse uue ebasobivat tüüpi patareiga, võib tekkida plahvatusoht. Tühjad patareid tuleb võimaluse korral viia vastavasse kogumispunkti. Tühjade patareide äraviskamisel tuleb järgida kohalikke keskkonnakaitse alaseid reegleid.

FIGYELMEZTETÉS

Ha az elemet nem a megfelelő típusúra cseréli, felrobbanhat. Az elemeket lehetőség szerint újra kell hasznosítani. A használt elemeket a helyi környezetvédelmi előírásoknak megfelelően kell kiselejtezni.

UZMANĪBU

Pastāv eksplozijas risks, ja baterijas tiek nomainītas ar nepareiza veida baterijām. Ja iespējams, baterijas vajadzētu nodot attiecīgos pieņemšanas punktos. Bateriju izmešanai atkritumos jānotiek saskaņā ar vietējiem vides aizsardzības noteikumiem.

DĖMESIO

Naudojant netinkamo tipo baterijas įrenginys gali sprogti. Kai tik įmanoma, baterijas reikia naudoti pakartotinai. Panaudotas baterijas išmesti būtina pagal vietinius aplinkos apsaugos nuostatus.

ATTENZJONI

Riskju ta' splużjoni jekk il-batterija tinbidel b'tip ta' batterija mhux korrett. Il-batteriji għandhom jiġu riċiklati fejn hu possibbli. Ir-rimi ta' batteriji użati għandu jsir skond ir-regolamenti ambjentali lokali.

OSTRZEŻENIE

Ryzyko wybuchu w przypadku wymiany na baterie niewłaściwego typu. W miarę możliwości baterie należy poddać recyklingowi. Zużytych baterii należy pozbywać się zgodnie z lokalnie obowiązującymi przepisami w zakresie ochrony środowiska.